



24AA00/24LC00/24C00	24AA01/24LC01B
24AA014/24LC014	24C01C
24AA02/24LC02B	24C02C
24AA024/24LC024	24AA025/24LC025
24AA04/24LC04B	24AA08/24LC08B
24AA16/24LC16B	24AA32A/24LC32A
24AA64/24LC64	24AA128/24LC128/24FC128
24AA256/24LC256/24FC256	24AA512/24LC512/24FC512

I²C™ Serial EEPROM Family Data Sheet

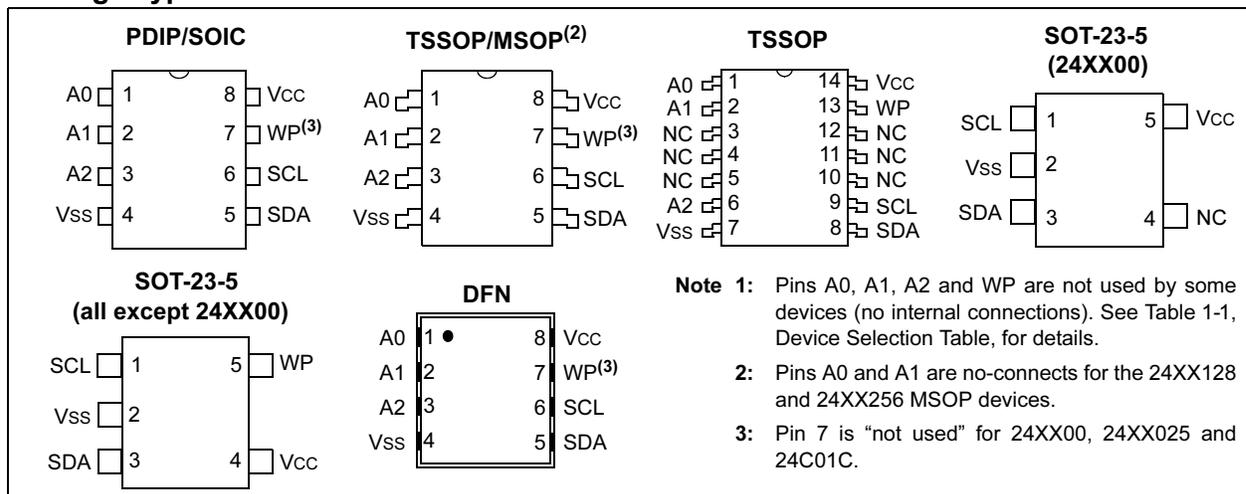
Features:

- 128-bit through 512 Kbit devices
- Single-supply with operation down to 1.8V for 24AAXX devices
- Low-power CMOS technology:
 - 1 mA active current typical
 - 1 μ A standby current typical (I-temp)
- 2-wire serial interface bus, I²C™ compatible
- Schmitt Trigger inputs for noise suppression
- Output slope control to eliminate ground bounce
- 100 kHz (1.8V) and 400 kHz (\geq 2.5V) compatibility
- 1 MHz for 24FCXX products
- Self-timed write cycle (including auto-erase)
- Page write buffer
- Hardware write-protect available on most devices
- Factory programming (QTP) available
- ESD protection > 4,000V
- 1 million erase/write cycles
- Data retention > 200 years
- 8-lead PDIP, SOIC, TSSOP and MSOP packages
- 5-lead SOT-23 package (most 1-16 Kbit devices)
- 8-lead 2x3mm and 5x6mm DFN packages available
- Available for extended temperature ranges:
 - Industrial (I): -40°C to +85°C
 - Automotive (E): -40°C to +125°C

Description:

The Microchip Technology Inc. 24CXX, 24LCXX, 24AAXX and 24FCXX (24XX*) devices are a family of 128-bit through 512 Kbit Electrically Erased PROMs. The devices are organized in blocks of x8-bit memory with 2-wire serial interfaces. Low voltage design permits operation down to 1.8V (for 24AAXX devices), with standby and active currents of only 1 μ A and 1 mA, respectively. Devices 1 Kbit and larger have page write capability. Parts having functional address lines allow connection of up to 8 devices on the same bus. The 24XX family is available in the standard 8-pin PDIP, surface mount SOIC, TSSOP and MSOP packages. Most 128-bit through 16 Kbit devices are also available in the 5-lead SOT-23 package. DFN packages (2x3mm or 5x6mm) are also available. All packages are available in a Pb-free (Matte Tin) finish.

Package Types⁽¹⁾



*24XX is used in this document as a generic part number for 24 series devices in this data sheet. 24XX64, for example, represents all voltages of the 64 Kbit device.

24AAXX/24LCXX/24FCXX

TABLE 1-1: DEVICE SELECTION TABLE

Part Number	Vcc Range	Max Clock Frequency	Page Size	Write-Protect Scheme	Functional Address Pins	Temp Range	Packages ⁽⁵⁾
128-bit devices							
24AA00	1.8-5.5V	400 kHz ⁽¹⁾	—	None	None	C, I	P, SN, ST, OT, MC
24LC00	2.5-5.5V	400 kHz ⁽¹⁾				C, I	
24C00	4.5-5.5V	400 kHz				C, I, E	
1 Kb devices							
24AA01	1.8-5.5V	400 kHz ⁽²⁾	8 bytes	Entire Array	None	I	P, SN, ST, MS, OT, MC
24LC01B	2.5-5.5V	400 kHz				I, E	
24AA014	1.8-5.5V	400 kHz ⁽²⁾	16 bytes	Entire Array	A0, A1, A2	I	P, SN, ST, MS, MC
24LC014	2.5-5.5V	400 kHz				I	
24C01C	4.5V-5.5V	400 kHz	16 bytes	None	A0, A1, A2	C, I, E	P, SN, ST, MC
2 Kb devices							
24AA02	1.8-5.5V	400 kHz ⁽²⁾	8 bytes	Entire Array	None	I	P, SN, ST, MS, OT, MC
24LC02B	2.5-5.5V	400 kHz				I, E	
24AA024	1.8-5.5V	400 kHz ⁽²⁾	16 bytes	Entire Array	A0, A1, A2	I	P, SN, ST, MS, MC
24LC024	2.5-5.5V	400 kHz				I	
24AA025	1.8-5.5V	400 kHz ⁽²⁾	16 bytes	None	A0, A1, A2	I	P, SN, ST, MS, MC
24LC025	2.5-5.5V	400 kHz				I	
24C02C	4.5-5.5V	400 kHz	16 bytes	Upper Half of Array	A0, A1, A2	C, I, E	P, SN, ST, MC
4 Kb devices							
24AA04	1.8-5.5V	400 kHz ⁽²⁾	16 bytes	Entire Array	None	I	P, SN, ST, MS, OT, MC
24LC04B	2.5-5.5V	400 kHz				I, E	
8 Kb devices							
24AA08	1.8-5.5V	400 kHz ⁽²⁾	16 bytes	Entire Array	None	I	P, SN, ST, MS, OT, MC
24LC08B	2.5-5.5V	400 kHz				I, E	
16 Kb devices							
24AA16	1.8-5.5V	400 kHz ⁽²⁾	16 bytes	Entire Array	None	I	P, SN, ST, MS, OT, MC
24LC16B	2.5-5.5V	400 kHz				I, E	
32 Kb devices							
24AA32A	1.8-5.5V	400 kHz ⁽²⁾	32 bytes	Entire Array	A0, A1, A2	I	P, SN, SM, ST, MS, MC
24LC32A	2.5-5.5V	400 kHz				I, E	
64 Kb devices							
24AA64	1.8-5.5V	400 kHz ⁽²⁾	32 bytes	Entire Array	A0, A1, A2	I	P, SN, SM, ST, MS, MC
24LC64	2.5-5.5V	400 kHz				I, E	

Note 1: 100 kHz for Vcc <4.5V.

2: 100 kHz for Vcc <2.5V.

3: 400 kHz for Vcc <2.5V

4: Pins A0 and A1 are no-connects for the 24XX128 and 24XX256 in the MSOP package.

5: P = 8-PDIP, SN = 8-SOIC (150 mil JEDEC), ST = 8-TSSOP, OT = 5 or 6-SOT23, MC = 2x3mm DFN, MS = 8-MSOP, SM = 8-SOIC (200 mil EIAJ), MF = 5x6mm DFN, ST14 = 14-TSSOP.

24AAXX/24LCXX/24FCXX

TABLE 1-1: DEVICE SELECTION TABLE (CONTINUED)

Part Number	Vcc Range	Max Clock Frequency	Page Size	Write-Protect Scheme	Functional Address Pins	Temp Range	Packages ⁽⁵⁾
128 Kb devices							
24AA128	1.8-5.5V	400 kHz ⁽²⁾	64 bytes	Entire Array	A0, A1, A2 ⁽⁴⁾	I	P, SN, SM, ST, MS, MF, ST14
24LC128	2.5-5.5V	400 kHz				I, E	
24FC128	1.8-5.5V	1 MHz ⁽³⁾				I	
256 Kb devices							
24AA256	1.8-5.5V	400 kHz ⁽²⁾	64 bytes	Entire Array	A0, A1, A2 ⁽⁴⁾	I	P, SN, SM, ST, MS, MF, ST14
24LC256	2.5-5.5V	400 kHz				I, E	
24FC256	1.8-5.5V	1 MHz ⁽³⁾				I	
512 Kb devices							
24AA512	1.8-5.5V	400 kHz ⁽²⁾	128 bytes	Entire Array	A0, A1, A2	I	P, SM, MF, ST14
24LC512	2.5-5.5V	400 kHz				I, E	
24FC512	1.8-5.5V ⁽³⁾	1 MHz				I	

Note 1: 100 kHz for Vcc <4.5V.

2: 100 kHz for Vcc <2.5V.

3: 400 kHz for Vcc <2.5V

4: Pins A0 and A1 are no-connects for the 24XX128 and 24XX256 in the MSOP package.

5: P = 8-PDIP, SN = 8-SOIC (150 mil JEDEC), ST = 8-TSSOP, OT = 5 or 6-SOT23, MC = 2x3mm DFN, MS = 8-MSOP, SM = 8-SOIC (200 mil EIAJ), MF = 5x6mm DFN, ST14 = 14-TSSOP.

24AAXX/24LCXX/24FCXX

2.0 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings ^(†)

V _{CC}	6.5V
All inputs and outputs w.r.t. V _{SS}	-0.6V to V _{CC} +1.0V
Storage temperature	-65°C to +150°C
Ambient temperature with power applied.....	-40°C to +125°C
ESD protection on all pins	≥ 4 kV

† NOTICE: Stresses above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operational listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

TABLE 2-1: DC CHARACTERISTICS

DC CHARACTERISTICS			Electrical Characteristics:				
			Commercial (C): V _{CC} = +1.8V to 5.5V TA = 0°C to +70°C				
			Industrial (I): V _{CC} = +1.8V to 5.5V TA = -40°C to +85°C				
			Automotive (E): V _{CC} = +2.5V to 5.5V TA = -40°C to 125°C				
Param. No.	Sym.	Characteristic	Min.	Max.	Units	Conditions	
D1	—	A0, A1, A2, SCL, SDA and WP pins:	—	—	—	—	
D2	V _{IH}	High-level input voltage	0.7 V _{CC}	—	V	—	
D3	V _{IL}	Low-level input voltage	—	0.3 V _{CC} 0.2 V _{CC}	V V	V _{CC} ≥ 2.5V V _{CC} < 2.5V	
D4	V _{HYS}	Hysteresis of Schmitt Trigger inputs (SDA, SCL pins)	0.05 V _{CC}	—	V	(Note 1)	
D5	V _{OL}	Low-level output voltage	—	0.40	V	I _{OL} = 3.0 mA @ V _{CC} = 2.5V	
D6	I _{LI}	Input leakage current	—	±1	μA	V _{IN} = V _{SS} or V _{CC}	
D7	I _{LO}	Output leakage current	—	±1	μA	V _{OUT} = V _{SS} or V _{CC}	
D8	C _{IN} , C _{OUT}	Pin capacitance (all inputs/outputs)	—	10	pF	V _{CC} = 5.0V (Note 1) TA = 25°C, F _{CLK} = 1 MHz	
D9	I _{CC} Read	Operating current	—	400	μA	24XX128, 256, 512: V _{CC} = 5.5V, SCL = 400 kHz All except 24XX128, 256, 512: V _{CC} = 5.5V, SCL = 400 kHz	
	1			mA			
	I _{CC} Write		—	3	mA	V _{CC} = 5.5V, All except 24XX512 V _{CC} = 5.5V, 24XX512	
				5	mA		
D10	I _{CCS}	Standby current	—	1	μA	TA = -40°C to +85°C SCL = SDA = V _{CC} = 5.5V A0, A1, A2, WP = V _{SS} or V _{CC}	
				5	μA		TA = -40°C to 125°C SCL = SDA = V _{CC} = 5.5V A0, A1, A2, WP = V _{SS} or V _{CC}
				50	μA		

Note 1: This parameter is periodically sampled and not 100% tested.

24AAXX/24LCXX/24FCXX

TABLE 2-2: AC CHARACTERISTICS – ALL EXCEPT 24XX00, 24C01C AND 24C02C

AC CHARACTERISTICS			Electrical Characteristics:			
			Industrial (I): V _{CC} = +1.8V to 5.5V TA = -40°C to +85°C			
			Automotive (E): V _{CC} = +2.5V to 5.5V TA = -40°C to 125°C			
Param. No.	Sym.	Characteristic	Min.	Max.	Units	Conditions
1	FCLK	Clock frequency	— — — —	100 400 400 1000	kHz	1.8V ≤ V _{CC} < 2.5V 2.5V ≤ V _{CC} ≤ 5.5V 1.8V ≤ V _{CC} < 2.5V 24FCXXX 2.5V ≤ V _{CC} ≤ 5.5V 24FCXXX
2	THIGH	Clock high time	4000 600 600 500	— — — —	ns	1.8V ≤ V _{CC} < 2.5V 2.5V ≤ V _{CC} ≤ 5.5V 1.8V ≤ V _{CC} < 2.5V 24FCXXX 2.5V ≤ V _{CC} ≤ 5.5V 24FCXXX
3	TLOW	Clock low time	4700 1300 1300 500	— — — —	ns	1.8V ≤ V _{CC} < 2.5V 2.5V ≤ V _{CC} ≤ 5.5V 1.8V ≤ V _{CC} < 2.5V 24FCXXX 2.5V ≤ V _{CC} ≤ 5.5V 24FCXXX
4	TR	SDA and SCL rise time (Note 1)	— — —	1000 300 300	ns	1.8V ≤ V _{CC} < 2.5V 2.5V ≤ V _{CC} ≤ 5.5V 1.8V ≤ V _{CC} ≤ 5.5V 24FCXXX
5	TF	SDA and SCL fall time (Note 1)	— —	300 100	ns	All except 24FCXXX 1.8V ≤ V _{CC} ≤ 5.5V 24FCXXX
6	THD:STA	Start condition hold time	4000 600 600 250	— — — —	ns	1.8V ≤ V _{CC} < 2.5V 2.5V ≤ V _{CC} ≤ 5.5V 1.8V ≤ V _{CC} < 2.5V 24FCXXX 2.5V ≤ V _{CC} ≤ 5.5V 24FCXXX
7	TSU:STA	Start condition setup time	4700 600 600 250	— — — —	ns	1.8V ≤ V _{CC} < 2.5V 2.5V ≤ V _{CC} ≤ 5.5V 1.8V ≤ V _{CC} < 2.5V 24FCXXX 2.5V ≤ V _{CC} ≤ 5.5V 24FCXXX
8	THD:DAT	Data input hold time	0	—	ns	(Note 2)
9	TSU:DAT	Data input setup time	250 100 100	— — —	ns	1.8V ≤ V _{CC} < 2.5V 2.5V ≤ V _{CC} ≤ 5.5V 1.8V ≤ V _{CC} ≤ 5.5V 24FCXXX
10	TSU:STO	Stop condition setup time	4000 600 600 250	— — — —	ns	1.8 V ≤ V _{CC} < 2.5V 2.5 V ≤ V _{CC} ≤ 5.5V 1.8V ≤ V _{CC} < 2.5V 24FCXXX 2.5 V ≤ V _{CC} ≤ 5.5V 24FCXXX
11	TSU:WP	WP setup time	4000 600 600	— — —	ns	1.8V ≤ V _{CC} < 2.5V 2.5V ≤ V _{CC} ≤ 5.5V 1.8V ≤ V _{CC} ≤ 5.5V 24FCXXX
12	THD:WP	WP hold time	4700 1300 1300	— — —	ns	1.8V ≤ V _{CC} < 2.5V 2.5V ≤ V _{CC} ≤ 5.5V 1.8V ≤ V _{CC} ≤ 5.5V 24FCXXX

Note 1: Not 100% tested. CB = total capacitance of one bus line in pF.

2: As a transmitter, the device must provide an internal minimum delay time to bridge the undefined region (minimum 300 ns) of the falling edge of SCL to avoid unintended generation of Start or Stop conditions.

3: This parameter is not tested but ensured by characterization. For endurance estimates in a specific application, please consult the Total Endurance™ Model, which can be obtained from Microchip's web site: www.microchip.com.

4: 24FCXXX denotes the 24FC128, 24FC256 and 24FC512 devices.

24AAXX/24LCXX/24FCXX

TABLE 2-2: AC CHARACTERISTICS – ALL EXCEPT 24XX00, 24C01C AND 24C02C (CONTINUED)

AC CHARACTERISTICS			Electrical Characteristics:			
			Industrial (I): $V_{CC} = +1.8V$ to $5.5V$ $T_A = -40^{\circ}C$ to $+85^{\circ}C$			
			Automotive (E): $V_{CC} = +2.5V$ to $5.5V$ $T_A = -40^{\circ}C$ to $125^{\circ}C$			
Param. No.	Sym.	Characteristic	Min.	Max.	Units	Conditions
13	TAA	Output valid from clock (Note 2)	— — — —	3500 900 900 400	ns	$1.8V \leq V_{CC} < 2.5V$ $2.5V \leq V_{CC} \leq 5.5V$ $1.8V \leq V_{CC} < 2.5V$ 24FCXXX $2.5V \leq V_{CC} \leq 5.5V$ 24FCXXX
14	TBUF	Bus free time: Time the bus must be free before a new transmission can start	4700 1300 1300 500	— — — —	ns	$1.8V \leq V_{CC} < 2.5V$ $2.5V \leq V_{CC} \leq 5.5V$ $1.8V \leq V_{CC} < 2.5V$ 24FCXXX $2.5V \leq V_{CC} \leq 5.5V$ 24FCXXX
15	ToF	Output fall time from V_{IH} minimum to V_{IL} maximum $C_B \leq 100$ pF	$10 + 0.1C_B$	250 250	ns	All except 24FCXXX (Note 1) 24FCXXX (Note 1)
16	TSP	Input filter spike suppression (SDA and SCL pins)	—	50	ns	All except 24FCXXX (Note 1)
17	TWC	Write cycle time (byte or page)	—	5	ms	
18	—	Endurance	1,000,000	—	cycles	$25^{\circ}C$ (Note 3)

Note 1: Not 100% tested. C_B = total capacitance of one bus line in pF.

2: As a transmitter, the device must provide an internal minimum delay time to bridge the undefined region (minimum 300 ns) of the falling edge of SCL to avoid unintended generation of Start or Stop conditions.

3: This parameter is not tested but ensured by characterization. For endurance estimates in a specific application, please consult the Total Endurance™ Model, which can be obtained from Microchip's web site: www.microchip.com.

4: 24FCXXX denotes the 24FC128, 24FC256 and 24FC512 devices.

24AAXX/24LCXX/24FCXX

TABLE 2-3: AC CHARACTERISTICS – 24XX00, 24C01C AND 24C02C

All Parameters apply across all recommended operating ranges unless otherwise noted		Commercial (C): TA = 0°C to +70°C, VCC = 1.8V to 5.5V Industrial (I): TA = -40°C to +85°C, VCC = 1.8V to 5.5V Automotive (E): TA = -40°C to +125°C, VCC = 4.5V to 5.5V			
Parameter	Symbol	Min	Max	Units	Conditions
Clock frequency	FCLK	—	100	kHz	4.5V ≤ VCC ≤ 5.5V (E Temp range)
		—	100		1.8V ≤ VCC ≤ 4.5V
		—	400		4.5V ≤ VCC ≤ 5.5V
Clock high time	THIGH	4000	—	ns	4.5V ≤ VCC ≤ 5.5V (E Temp range)
		4000	—		1.8V ≤ VCC ≤ 4.5V
		600	—		4.5V ≤ VCC ≤ 5.5V
Clock low time	TLOW	4700	—	ns	4.5V ≤ VCC ≤ 5.5V (E Temp range)
		4700	—		1.8V ≤ VCC ≤ 4.5V
		1300	—		4.5V ≤ VCC ≤ 5.5V
SDA and SCL rise time (Note 1)	TR	—	1000	ns	4.5V ≤ VCC ≤ 5.5V (E Temp range)
		—	1000		1.8V ≤ VCC ≤ 4.5V
		—	300		4.5V ≤ VCC ≤ 5.5V
SDA and SCL fall time	TF	—	300	ns	(Note 1)
Start condition hold time	THD:STA	4000	—	ns	4.5V ≤ VCC ≤ 5.5V (E Temp range)
		4000	—		1.8V ≤ VCC ≤ 4.5V
		600	—		4.5V ≤ VCC ≤ 5.5V
Start condition setup time	TSU:STA	4700	—	ns	4.5V ≤ VCC ≤ 5.5V (E Temp range)
		4700	—		1.8V ≤ VCC ≤ 4.5V
		600	—		4.5V ≤ VCC ≤ 5.5V
Data input hold time	THD:DAT	0	—	ns	(Note 2)
Data input setup time	TSU:DAT	250	—	ns	4.5V ≤ VCC ≤ 5.5V (E Temp range)
		250	—		1.8V ≤ VCC ≤ 4.5V
		100	—		4.5V ≤ VCC ≤ 5.5V
Stop condition setup time	TSU:STO	4000	—	ns	4.5V ≤ VCC ≤ 5.5V (E Temp range)
		4000	—		1.8V ≤ VCC ≤ 4.5V
		600	—		4.5V ≤ VCC ≤ 5.5V
Output valid from clock (Note 2)	TAA	—	3500	ns	4.5V ≤ VCC ≤ 5.5V (E Temp range)
		—	3500		1.8V ≤ VCC ≤ 4.5V
		—	900		4.5V ≤ VCC ≤ 5.5V
Bus free time: Time the bus must be free before a new transmission can start	TBUF	4700	—	ns	4.5V ≤ VCC ≤ 5.5V (E Temp range)
		4700	—		1.8V ≤ VCC ≤ 4.5V
		1300	—		4.5V ≤ VCC ≤ 5.5V
Output fall time from VIH minimum to VIL maximum	TOF	20+0.1 CB	250	ns	(Note 1), CB ≤ 100 pF
Input filter spike suppression (SDA and SCL pins)	TSP	—	50	ns	(Note 1)
Write cycle time	TWC	—	4	ms	24XX00
			1.5		24C01C, 24C02C
Endurance		1,000,000	—	cycles	(Note 3)

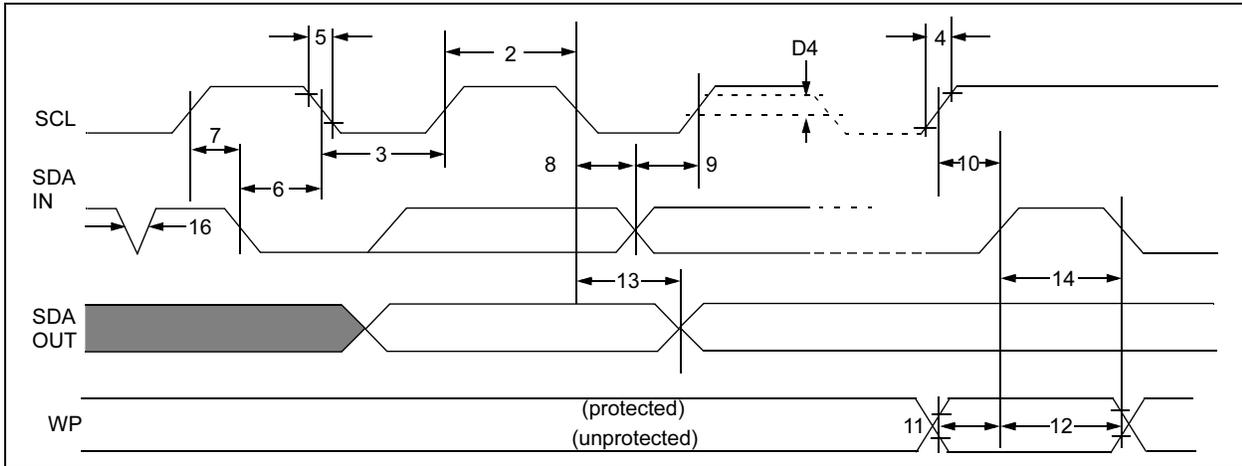
Note 1: Not 100% tested. CB = total capacitance of one bus line in pF.

2: As a transmitter, the device must provide an internal minimum delay time to bridge the undefined region (minimum 300 ns) of the falling edge of SCL to avoid unintended generation of Start or Stop conditions.

3: This parameter is not tested but ensured by characterization. For endurance estimates in a specific application, please consult the Total Endurance™ Model which can be obtained at www.microchip.com.

24AAXX/24LCXX/24FCXX

FIGURE 2-1: BUS TIMING DATA



3.0 PIN DESCRIPTIONS

The descriptions of the pins are listed in Table 3-1.

TABLE 3-1: PIN FUNCTION TABLE

Pin Name	8-Pin PDIP and SOIC	8-Pin TSSOP and MSOP	5-Pin SOT-23 24XX00	5-Pin SOT-23 All except 24XX00	14-Pin TSSOP	8-Pin 5x6 DFN and 2x3 DFN	Function
A0	1	1 ⁽¹⁾	—	—	1	1	User configurable Chip Select ⁽³⁾
A1	2	2 ⁽¹⁾	—	—	2	2	User configurable Chip Select ⁽³⁾
A2	3	3	—	—	6	3	User configurable Chip Select ⁽³⁾
Vss	4	4	2	2	7	4	Ground
SDA	5	5	3	3	8	5	Serial Data
SCL	6	6	1	1	9	6	Serial Clock
(NC)	—	—	4	—	3, 4, 5, 10, 11, 12	—	Not Connected
WP	7 ⁽²⁾	7 ⁽²⁾	—	5	13	7	Write-Protect Input
Vcc	8	8	5	4	14	8	Power Supply

Note 1: Pins 1 and 2 are not connected for the 24XX128 and 24XX256 MSOP packages.

2: Pin 7 is not used for 24XX00, 24XX025 and 24C01C.

3: Pins A0, A1 and A2 are not used by some devices (no internal connections). See Table 1-1 for details.

3.1 A0, A1, A2 Chip Address Inputs

The A0, A1 and A2 pins are not used by the 24XX01 through 24XX16 devices.

The A0, A1 and A2 inputs are used by the 24C01C, 24C02C, 24XX014, 24XX024, 24XX025 and the 24XX32 through 24XX512 for multiple device operations. The levels on these inputs are compared with the corresponding bits in the slave address. The chip is selected if the compare is true.

For the 24XX128 and 24XX256 in the MSOP package only, pins A0 and A1 are not connected.

Up to eight devices (two for the 24XX128 and 24XX256 MSOP package) may be connected to the same bus by using different Chip Select bit combinations.

In most applications, the chip address inputs A0, A1 and A2 are hard-wired to logic '0' or logic '1'. For applications in which these pins are controlled by a microcontroller or other programmable device, the chip address pins must be driven to logic '0' or logic '1' before normal device operation can proceed.

3.2 Serial Data (SDA)

This is a bidirectional pin used to transfer addresses and data into and out of the device. It is an open drain terminal. Therefore, the SDA bus requires a pull-up resistor to Vcc (typical 10 kΩ for 100 kHz, 2 kΩ for 400 kHz and 1 MHz).

For normal data transfer, SDA is allowed to change only during SCL low. Changes during SCL high are reserved for indicating the Start and Stop conditions.

3.3 Serial Clock (SCL)

This input is used to synchronize the data transfer to and from the device.

3.4 Write-Protect (WP)

This pin must be connected to either Vss or Vcc. If tied to Vss, write operations are enabled. If tied to Vcc, write operations are inhibited but read operations are not affected. See Table 1-1 for the write-protect scheme of each device.

3.5 Power Supply (Vcc)

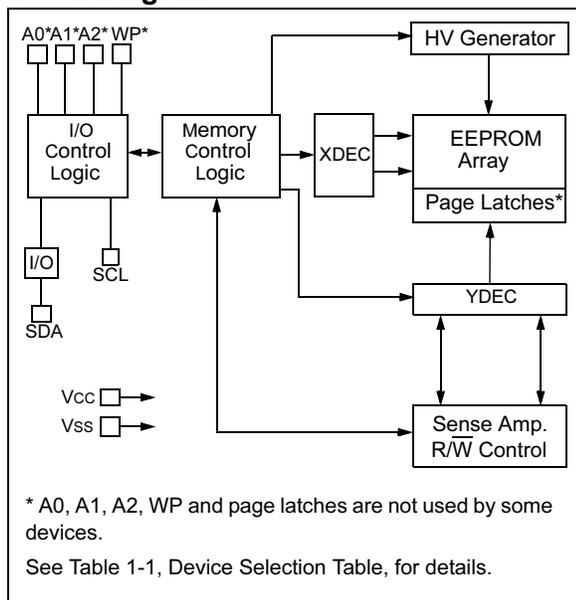
A Vcc threshold detect circuit is employed which disables the internal erase/write logic if Vcc is below 1.5V at nominal conditions. For the 24C00, 24C01C and 24C02C devices, the erase/write logic is disabled below 3.8V at nominal conditions.

24AAXX/24LCXX/24FCXX

4.0 FUNCTIONAL DESCRIPTION

Each 24XX device supports a bidirectional, 2-wire bus and data transmission protocol. A device that sends data onto the bus is defined as a transmitter, while a device receiving data is defined as a receiver. The bus has to be controlled by a master device which generates the Serial Clock (SCL), controls the bus access and generates the Start and Stop conditions, while the 24XX works as slave. Both master and slave can operate as transmitter or receiver, but the master device determines which mode is activated.

Block Diagram



5.0 BUS CHARACTERISTICS

The following **bus protocol** has been defined:

- Data transfer may be initiated only when the bus is not busy.
- During data transfer, the data line must remain stable whenever the clock line is high. Changes in the data line while the clock line is high will be interpreted as a Start or Stop condition.

Accordingly, the following bus conditions have been defined (Figure 5-1).

5.1 Bus Not Busy (A)

Both data and clock lines remain high.

5.2 Start Data Transfer (B)

A high-to-low transition of the SDA line while the clock (SCL) is high determines a Start condition. All commands must be preceded by a Start condition.

5.3 Stop Data Transfer (C)

A low-to-high transition of the SDA line while the clock (SCL) is high determines a Stop condition. All operations must be ended with a Stop condition.

5.4 Data Valid (D)

The state of the data line represents valid data when, after a Start condition, the data line is stable for the duration of the high period of the clock signal.

The data on the line must be changed during the low period of the clock signal. There is one clock pulse per bit of data.

Each data transfer is initiated with a Start condition and terminated with a Stop condition. The number of data bytes transferred between Start and Stop conditions is determined by the master device.

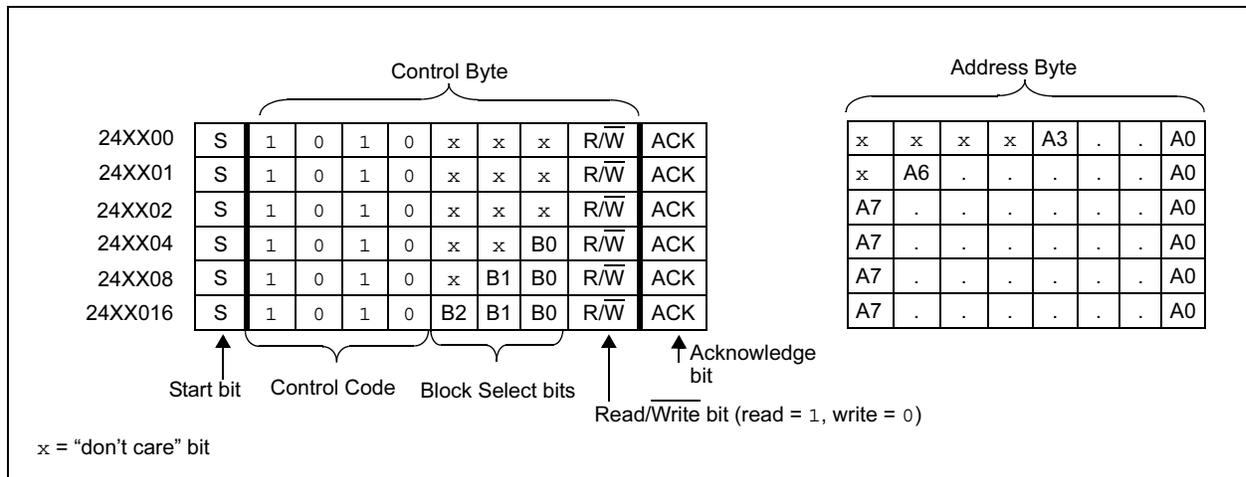
24AAXX/24LCXX/24FCXX

5.6 Device Addressing For Devices Without Functional Address Pins

A control byte is the first byte received following the Start condition from the master device (Figure 5-3). The control byte begins with a four-bit control code. For the 24XX, this is set as '1010' binary for read and write operations. The next three bits of the control byte are the block-select bits (B2, B1, B0). They are used by the master device to select which of the 256-word blocks of memory are to be accessed. These bits are in effect the three Most Significant bits of the word address. Note that B2, B1 and B0 are "don't care" for the 24XX00, the 24XX01 and 24XX02. B2 and B1 are "don't care" for the 24XX04. B2 is "don't care" for the 24XX08.

The last bit of the control byte defines the operation to be performed. When set to '1', a read operation is selected. When set to '0' a write operation is selected. Following the Start condition, the 24XX monitors the SDA bus. Upon receiving a '1010' code, the block select bits and the R/W bit, the slave device outputs an Acknowledge signal on the SDA line. The address byte follows the acknowledge.

FIGURE 5-3: CONTROL AND ADDRESS BYTE ASSIGNMENTS FOR DEVICES WITHOUT ADDRESS PINS



24AAXX/24LCXX/24FCXX

5.7 Device Addressing For Devices With Functional Address Pins

A control byte is the first byte received following the Start condition from the master device (Figure 5-4). The control byte begins with a 4-bit control code. For the 24XX, this is set as '1010' binary for read and write operations. The next three bits of the control byte are the Chip Select bits (A2, A1, A0). The Chip Select bits allow the use of up to eight 24XX devices on the same bus and are used to select which device is accessed. The Chip Select bits in the control byte must correspond to the logic levels on the corresponding A2, A1 and A0 pins for the device to respond. These bits are, in effect, the three Most Significant bits of the word address.

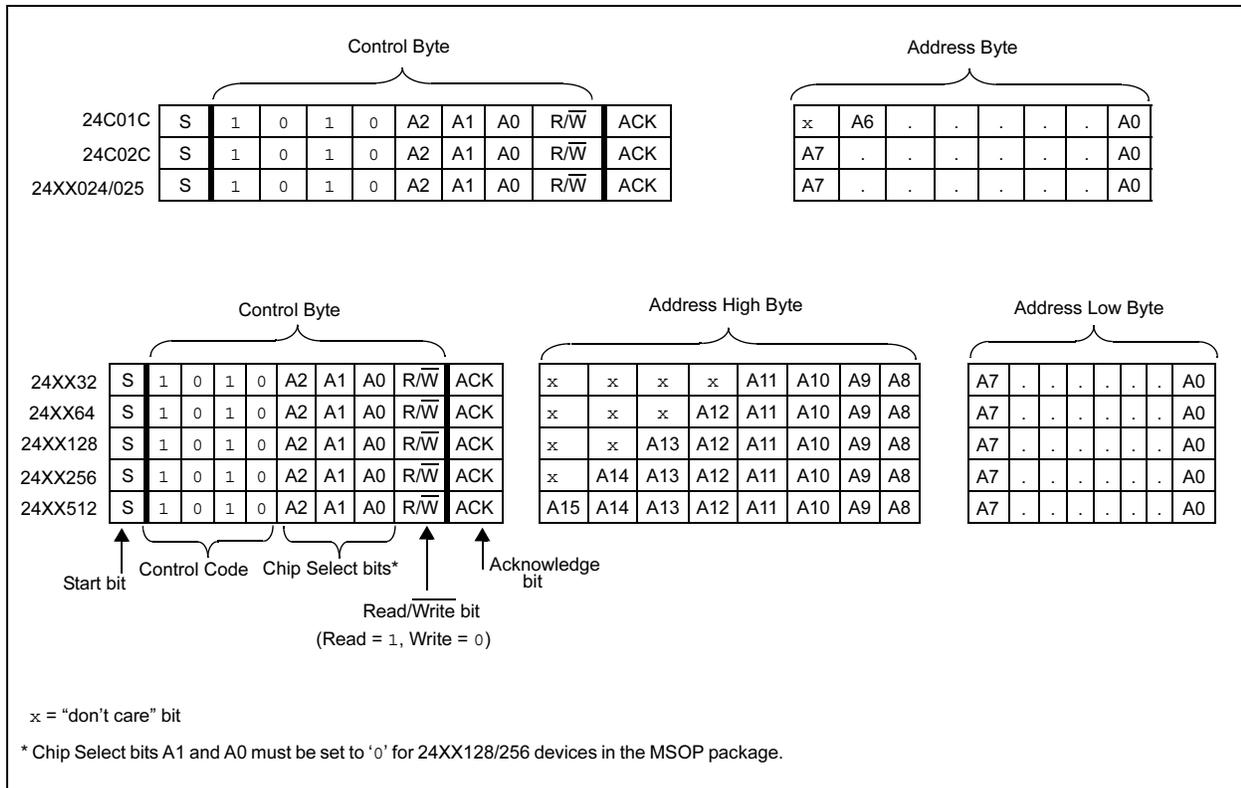
For 24XX128 and 24XX256 in the MSOP package, the A0 and A1 pins are not connected. During device addressing, the A0 and A1 Chip Select bits (Figure 5-4) should be set to '0'. Only two 24XX128 or 24XX256 MSOP packages can be connected to the same bus.

The last bit of the control byte defines the operation to be performed. When set to a '1', a read operation is selected. When set to a '0', a write operation is selected.

For higher density devices (24XX32 through 24XX512), the next two bytes received define the address of the first data byte. Depending on the product density, not all bits in the address high byte are used. A15, A14, A13 and A12 are "don't care" for 24XX32. A15, A14 and A13 are "don't care" for 24XX64. A15 and A14 are "don't care" for 24XX128. A15 is "don't care" for 24XX256. All address bits are used for the 24XX512. The upper address bits are transferred first, followed by the Less Significant bits.

Following the Start condition, the 24XX monitors the SDA bus. Upon receiving a '1010' code, appropriate device select bits and the R/W bit, the slave device outputs an Acknowledge signal on the SDA line. The address byte(s) follow the acknowledge.

FIGURE 5-4: CONTROL AND ADDRESS BYTE ASSIGNMENTS FOR DEVICES WITH ADDRESS PINS



5.7.1 CONTIGUOUS ADDRESSING ACROSS MULTIPLE DEVICES

Chip Select bits A2, A1 and A0 can be used to expand the contiguous address space by adding up to eight 24XXs on the same bus. Software can use the three address bits of the control byte as the three Most Significant bits of the address byte. For example, in the 24XX32 devices, software can use A0 of the **control byte** as address bit A12; A1 as address bit A13; and A2 as address bit A14 (Table 5-1). It is not possible to sequentially read across device boundaries.

TABLE 5-1: CONTROL BYTE ADDRESS BITS

	Maximum Devices	Maximum Contiguous Address Space	Chip Select Bit A2	Chip Select Bit A1	Chip Select Bit A0
1K (24C01C)	8	8 Kb	A10	A9	A8
1K (24XX014)	8	8 Kb	A10	A9	A8
2K (24C02C)	8	16 Kb	A10	A9	A8
2K (24XX024/025)	8	16 Kb	A10	A9	A8
32K (24XX32)	8	256 Kb	A14	A13	A12
64K (24XX64)	8	512 Kb	A15	A14	A13
128K (24XX128)	8*	1 Mb	A16*	A15*	A14
256K (24XX256)	8*	2 Mb	A17*	A16*	A15
512K (24XX512)	8	4 Mb	A18	A17	A16

* Up to two 24XX128 or 24XX256 devices in the MSOP package can be added for up to 256 kb or 512 kb of address space, respectively. Bits A0 and A1 must be set to '0'.

24AAXX/24LCXX/24FCXX

6.0 WRITE OPERATIONS

6.1 Byte Write

A byte write operation begins with a Start condition from the master followed by the four-bit control code (see Figure 6-1 and Figure 6-2). The next 3 bits are either the Block Address bits (for devices without address pins) or the Chip Select bits (for devices with address pins). Then the master transmits the R/W bit (which is a logic low) onto the bus. The slave then generates an Acknowledge bit during the ninth clock cycle.

The next byte transmitted by the master is the address byte (for 128-bit to 16 Kbit devices) or the high-order address byte (for 32-512 Kbit devices). For 32 through 512 Kbit devices, the high-order address byte is followed by the low-order address byte. In either case, each address byte is acknowledged by the 24XX and the address bits are latched into the internal address counter of the 24XX.

For the 24XX00 devices, only the lower four address bits are used by the device. The upper four bits are “don’t cares.”

After receiving the ACK from the 24XX acknowledging the final address byte, the master device transmits the data word to be written into the addressed memory location. The 24XX acknowledges again and the master generates a Stop condition, which initiates the internal write cycle.

If an attempt is made to write to an array with the WP pin held high, the device will acknowledge the command, but no write cycle will occur, no data will be written, and the device will immediately accept a new command. After a byte Write command, the internal address counter will increment to the next address location. During a write cycle, the 24XX will not acknowledge commands.

FIGURE 6-1: BYTE WRITE: 128-BIT TO 16 KBIT DEVICES

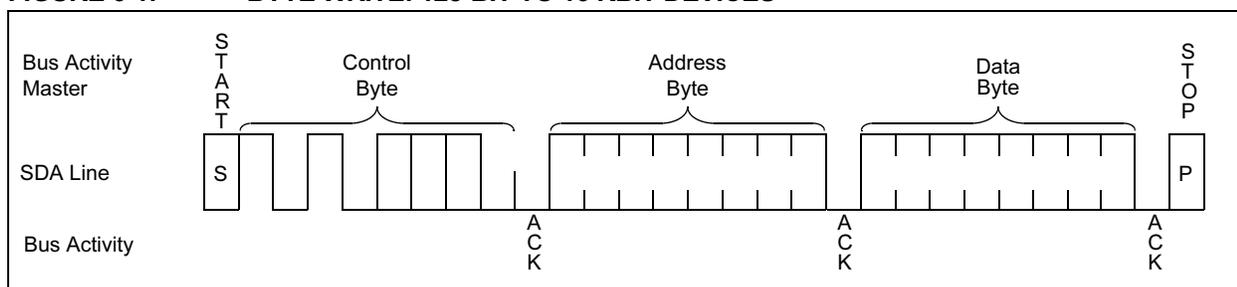
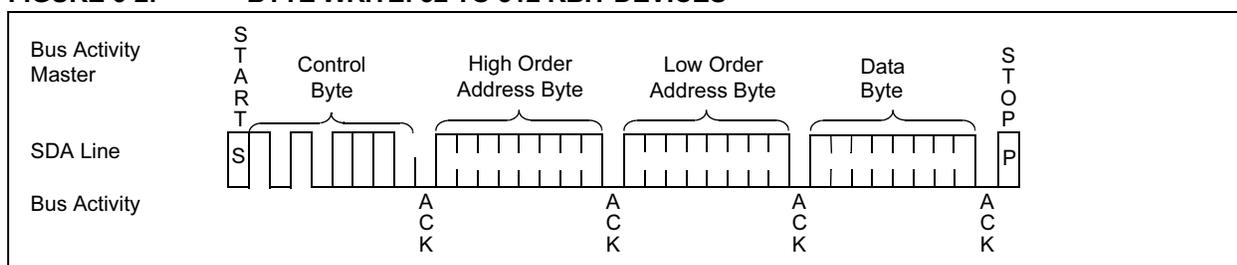


FIGURE 6-2: BYTE WRITE: 32 TO 512 KBIT DEVICES



6.2 Page Write

The write control byte, word address byte(s), and the first data byte are transmitted to the 24XX in much the same way as in a byte write (see Figure 6-3 and Figure 6-4). The exception is that instead of generating a Stop condition, the master transmits up to one page of bytes⁽¹⁾, which is temporarily stored in the on-chip page buffer. This data is then written into memory once the master has transmitted a Stop condition. Upon receipt of each word, the internal address counter is incremented by one. If the master should transmit more than one page of data prior to generating the Stop condition, the address counter will roll over and the previously received data will be overwritten. As with the byte write operation, once the Stop condition is received, an internal write cycle begins. During the write cycle, the 24XX will not acknowledge commands.

Page writes can be any number of bytes within a page (up to the page size), starting at any address. Only the data bytes being addressed will be changed within the page.

If an attempt is made to write to the array with the WP pin held high, the device will acknowledge the command, but no write cycle will occur, no data will be written and the device will immediately accept a new command.

Note 1: See Device Selection Table 1-1 for the page size of each device.

6.3 Write-Protection

The WP pin allows the user to write-protect the array when the pin is tied to VCC. See Device Selection Table 1-1 for the write-protect scheme of each device. If tied to VSS, the write protection is disabled. The WP pin is sampled prior to the Stop bit for every Write command (Figure 2-1). Toggling the WP pin after the Stop bit will have no effect on the execution of the write cycle.

Note: Page write operations are limited to writing bytes within a single physical page, **regardless** of the number of bytes actually being written. Physical page boundaries start at addresses that are integer multiples of the page buffer size (or 'page size') and end at addresses that are integer multiples of [page size - 1]. If a Page Write command attempts to write across a physical page boundary, the result is that the data wraps around to the beginning of the current page (overwriting data previously stored there), instead of being written to the next page, as might be expected. It is therefore necessary for the application software to prevent page write operations that would attempt to cross a page boundary.

FIGURE 6-3: PAGE WRITE: 1 KB TO 16 KBIT DEVICES

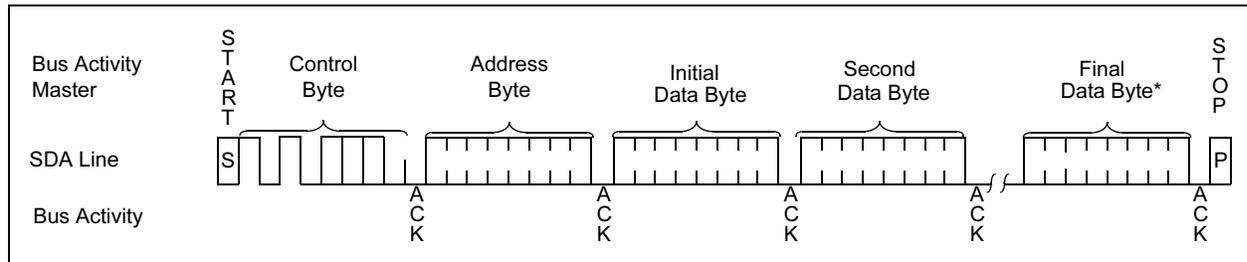
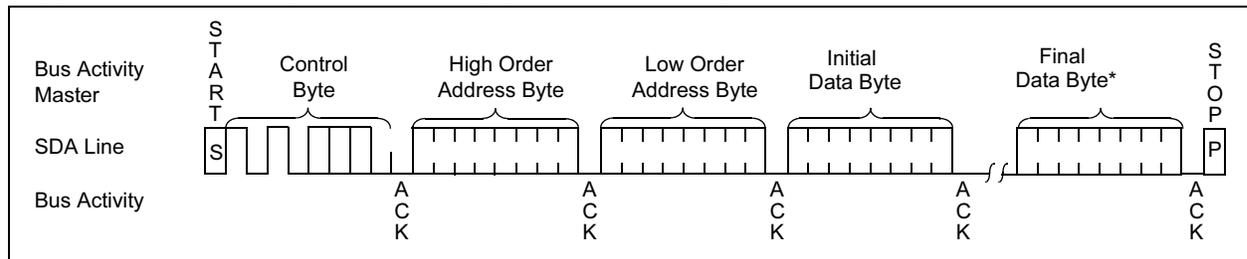


FIGURE 6-4: PAGE WRITE: 32 TO 512 KBIT DEVICES



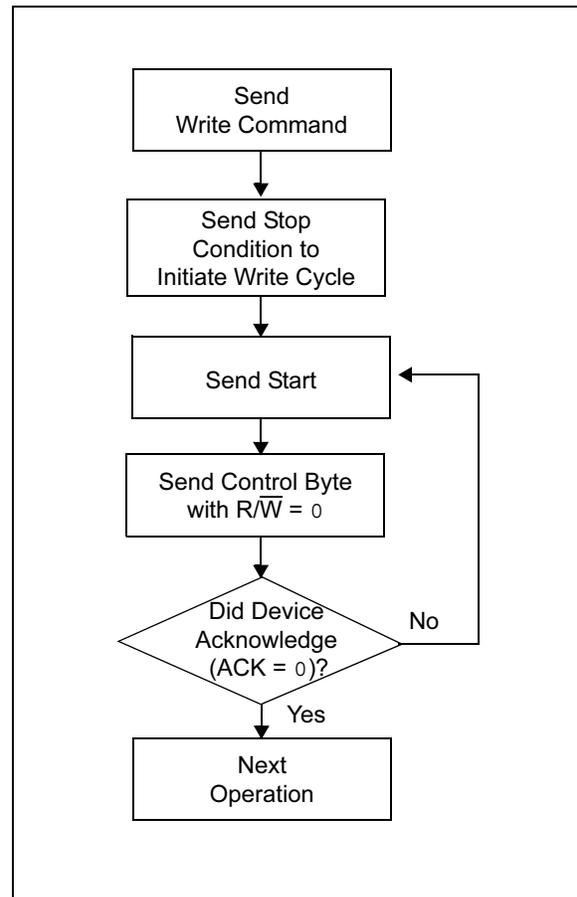
* See Table 1-1 for maximum number of data bytes in a page.

24AAXX/24LCXX/24FCXX

7.0 ACKNOWLEDGE POLLING

Since the device will not acknowledge commands during a write cycle, this can be used to determine when the cycle is complete (This feature can be used to maximize bus throughput). Once the Stop condition for a Write command has been issued from the master, the device initiates the internally timed write cycle. ACK polling can be initiated immediately. This involves the master sending a Start condition, followed by the control byte for a Write command ($R/\overline{W} = 0$). If the device is still busy with the write cycle, then no ACK will be returned. If no ACK is returned, the Start bit and control byte must be re-sent. If the cycle is complete, then the device will return the ACK and the master can then proceed with the next Read or Write command. See Figure 7-1 for flow diagram.

FIGURE 7-1: ACKNOWLEDGE POLLING FLOW



8.0 READ OPERATION

Read operations are initiated in much the same way as write operations with the exception that the R/\overline{W} bit of the control byte is set to '1'. There are three basic types of read operations: current address read, random read and sequential read.

8.1 Current Address Read

The 24XX contains an address counter that maintains the address of the last byte accessed, internally incremented by '1'. Therefore, if the previous read or write operation was to address 'n' (n is any legal address), the next current address read operation would access data from address $n + 1$.

Upon receipt of the control byte with R/\overline{W} bit set to '1', the 24XX issues an acknowledge and transmits the 8-bit data byte. The master will not acknowledge the transfer, but does generate a Stop condition and the 24XX discontinues transmission (Figure 8-1).

8.2 Random Read

Random read operations allow the master to access any memory location in a random manner. To perform this type of read operation, the byte address must first be set. This is done by sending the byte address to the 24XX as part of a write operation (R/\overline{W} bit set to '0'). Once the byte address is sent, the master generates a Start condition following the acknowledge. This terminates the write operation, but not before the internal address counter is set. The master then issues the control byte again, but with the R/\overline{W} bit set to a '1'. The 24XX will then issue an acknowledge and transmit the 8-bit data byte. The master will not acknowledge the transfer but does generate a Stop condition, which causes the 24XX to discontinue transmission (Figure 8-2 and Figure 8-3). After a random Read command, the internal address counter will increment to the next address location.

FIGURE 8-1: CURRENT ADDRESS READ

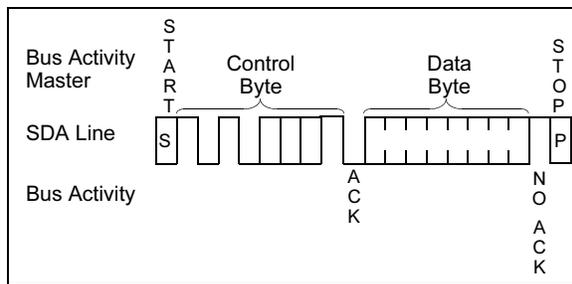


FIGURE 8-2: RANDOM READ: 128-BIT TO 16 KBIT DEVICES

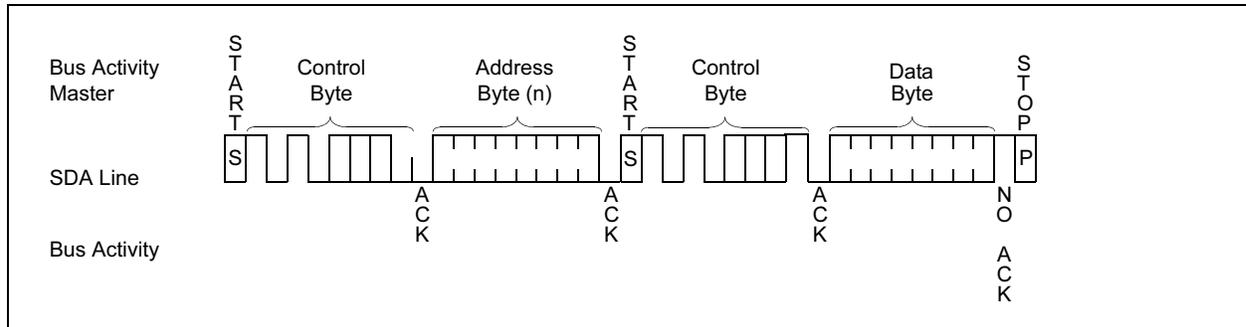
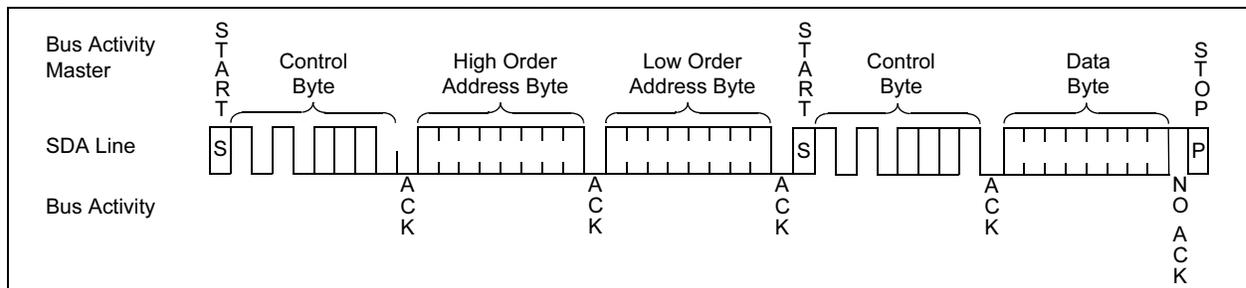


FIGURE 8-3: RANDOM READ: 32 TO 512 KBIT DEVICES

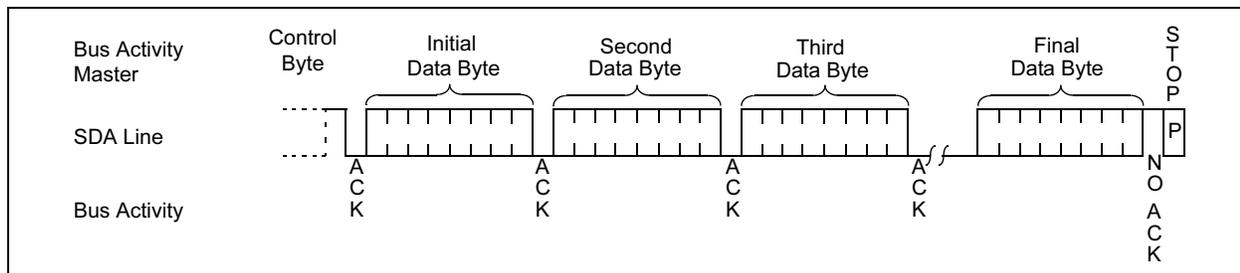


24AAXX/24LCXX/24FCXX

8.3 Sequential Read

Sequential reads are initiated in the same way as a random read except that after the 24XX transmits the first data byte, the master issues an acknowledge as opposed to the Stop condition used in a random read. This acknowledge directs the 24XX to transmit the next sequentially addressed data byte (Figure 8-4). Following the final byte transmitted to the master, the master will NOT generate an acknowledge but will generate a Stop condition. To provide sequential reads, the 24XX contains an internal address pointer which is incremented by one at the completion of each operation. This address pointer allows the entire memory contents to be serially read during one operation. If the last address byte in the array is acknowledged, the address pointer will roll over to address 0x00.

FIGURE 8-4: SEQUENTIAL READ



APPENDIX A: REVISION HISTORY

Revision A

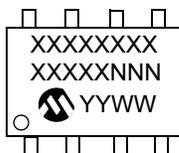
Original release of document. Combined Serial EEPROM 24XXX device data sheets.

24AAXX/24LCXX/24FCXX

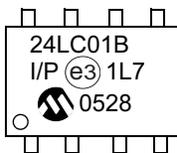
9.0 PACKAGING INFORMATION

9.1 Package Marking Information

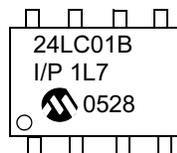
8-Lead PDIP



Example: Pb-free



Example: Sn/Pb



8-Lead PDIP Package Marking (Pb-free)

Device	Line 1 Marking	Device	Line 1 Marking	Device	Line 1 Marking	Device	Line 1 Marking
24AA00	24AA00	24LC00	24LC00	24C00	24C00		
24AA01	24AA01	24LC01B	24LC01B				
24AA014	24AA014	24LC014	24LC014				
				24C01C	24C01C		
24AA02	24AA02	24LC02B	24LC02B				
24AA024	24AA024	24LC024	24LC024				
24AA025	24AA025	24LC025	24LC025				
				24C02C	24C02C		
24AA04	24AA04	24LC04B	24LC04B				
24AA08	24AA08	24LC08B	24LC08B				
24AA16	24AA16	24LC16B	24LC16B				
24AA32A	24AA32A	24LC32A	24LC32A				
24AA64	24AA64	24LC64	24LC64				
24AA128	24AA128	24LC128	24LC128			24FC128	24FC128
24AA256	24AA256	24LC256	24LC256			24FC256	24FC256
24AA512	24AA512	24LC512	24LC512			24FC512	24FC512

Legend: XX...X Part number or part number code
 Y Year code (last digit of calendar year)
 YY Year code (last 2 digits of calendar year)
 WW Week code (week of January 1 is week '01')
 NNN Alphanumeric traceability code (2 characters for small packages)
 (e3) Pb-free JEDEC designator for Matte Tin (Sn) plated devices

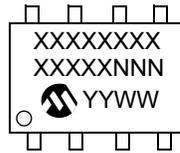
Note: For very small packages with no room for the Pb-free JEDEC designator (e3), the marking will only appear on the outer carton or reel label.

Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information.

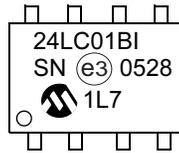
Note: Please visit www.microchip.com/Pbfree for the latest information on Pb-free conversion.

24AAXX/24LCXX/24FCXX

8-Lead SOIC



Example: Pb-free



Example: Sn/Pb



8-Lead SOIC Package Marking (Pb-free)							
Device	Line 1 Marking	Device	Line 1 Marking	Device	Line 1 Marking	Device	Line 1 Marking
24AA00	24AA00T	24LC00	24LC00T	24C00	24C00T		
24AA01	24AA01T	24LC01B	24LC01BT				
24AA014	24AA014T	24LC014	24LC014T				
				24C01C	24C01CT		
24AA02	24AA02T	24LC02B	24LC02BT				
24AA024	24AA024T	24LC024	24LC024T				
24AA025	24AA025T	24LC025	24LC025T				
				24C02C	24C02CT		
24AA04	24AA04T	24LC04B	24LC04BT				
24AA08	24AA08T	24LC08B	24LC08BT				
24AA16	24AA16T	24LC16B	24LC16BT				
24AA32A	24AA32AT	24LC32A	24LC32AT				
24AA64	24AA64T	24LC64	24LC64T				
24AA128	24AA128T	24LC128	24LC128T			24FC128	24FC128T
24AA256	24AA256T	24LC256	24LC256T			24FC256	24FC256T
24AA512	24AA512T	24LC512	24LC512T			24FC512	24FC512T

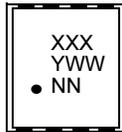
Note: T = Temperature range: I = Industrial, E = Extended, (blank) = Commercial

<p>Legend: XX...X Part number or part number code Y Year code (last digit of calendar year) YY Year code (last 2 digits of calendar year) WW Week code (week of January 1 is week '01') NNN Alphanumeric traceability code (2 characters for small packages) (e3) Pb-free JEDEC designator for Matte Tin (Sn) plated devices</p>
<p>Note: For very small packages with no room for the Pb-free JEDEC designator (e3), the marking will only appear on the outer carton or reel label.</p> <p>Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information.</p>

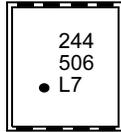
Note: Please visit www.microchip.com/Pbfree for the latest information on Pb-free conversion.

24AAXX/24LCXX/24FCXX

8-Lead 2x3 DFN



Example:



8-Lead 2x3mm DFN Package Marking (Pb-free)

Device	Industrial Line 1 Marking	Device	Industrial Line 1 Marking	E-Temp Line 1 Marking	Device	Industrial Line 1 Marking	E-Temp Line 1 Marking
24AA00	201	24LC00	204	205	24C00	207	208
24AA01	211	24LC01B	214	215			
24AA014	2N1	24LC014	2N4	2N5			
					24C01C	2N7	2N8
24AA02	221	24LC02B	224	225			
24AA024	2P1	24LC024	2P4	2P5			
24AA025	2R1	24LC025	2R4	2R5			
					24C02C	2P7	2P8
24AA04	231	24LC04B	234	235			
24AA08	241	24LC08B	244	245			
24AA16	251	24LC16B	254	255			
24AA32A	261	24LC32A	264	265			
24AA64	271	24LC64	274	275			

Legend: XX...X Part number or part number code
 Y Year code (last digit of calendar year)
 YY Year code (last 2 digits of calendar year)
 WW Week code (week of January 1 is week '01')
 NNN Alphanumeric traceability code (2 characters for small packages)
 (e3) Pb-free JEDEC designator for Matte Tin (Sn) plated devices

Note: For very small packages with no room for the Pb-free JEDEC designator (e3), the marking will only appear on the outer carton or reel label.

Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information.

24AAXX/24LCXX/24FCXX

8-Lead DFN



Example: Pb-free



Example: Sn/Pb



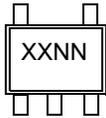
8-Lead 5x6mm DFN Package Marking (Pb-free)					
Device	Line 1 Marking	Device	Line 1 Marking	Device	Line 1 Marking
24AA128	24AA128	24LC128	24LC128	24FC128	24FC128
24AA256	24AA256	24LC256	24LC256	24FC256	24FC256
24AA512	24AA512	24LC512	24LC512	24FC512	24FC512

Note: Temperature range (T) listed on second line. I = Industrial, E = Extended

<p>Legend: XX...X Part number or part number code Y Year code (last digit of calendar year) YY Year code (last 2 digits of calendar year) WW Week code (week of January 1 is week '01') NNN Alphanumeric traceability code (2 characters for small packages) (e3) Pb-free JEDEC designator for Matte Tin (Sn) plated devices</p>
<p>Note: For very small packages with no room for the Pb-free JEDEC designator (e3), the marking will only appear on the outer carton or reel label.</p>
<p>Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information.</p>

24AAXX/24LCXX/24FCXX

5-Lead SOT-23



Example:



5-Lead SOT-23 Package Marking (Pb-free)										
Device	Comm. Marking	Indust. Marking	Device	Comm. Marking	Indust. Marking	E-Temp Marking	Device	Comm. Marking	Indust. Marking	E-Temp Marking
24AA00	A0NN	B0NN	24LC00	L0NN	M0NN	N0NN	24C00	C0NN	D0NN	E0NN
24AA01	A1NN	B1NN	24LC01B	L1NN	M1NN	N1NN				
24AA02	A2NN	B2NN	24LC02B	L2NN	M2NN	N2NN				
24AA04	A3NN	B3NN	24LC04B	L3NN	M3NN	N3NN				
24AA08	A4NN	B4NN	24LC08B	L4NN	M4NN	N4NN				
24AA16	A5NN	B5NN	24LC16B	L5NN	M5NN	N5NN				

Legend: XX...X Part number or part number code
 Y Year code (last digit of calendar year)
 YY Year code (last 2 digits of calendar year)
 WW Week code (week of January 1 is week '01')
 NNN Alphanumeric traceability code (2 characters for small packages)
 (e3) Pb-free JEDEC designator for Matte Tin (Sn) plated devices

Note: For very small packages with no room for the Pb-free JEDEC designator (e3), the marking will only appear on the outer carton or reel label.

Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information.

24AAXX/24LCXX/24FCXX

8-Lead MSOP (150 mil)



Example:



8-Lead MSOP Package Marking (Pb-free)							
Device	Line 1 Marking	Device	Line 1 Marking	Device	Line 1 Marking	Device	Line 1 Marking
24AA01	4A01T	24LC01B	4L1BT				
24AA014	4A14T	24LC014	4L14T				
				24C01C	4C1CT		
24AA02	4A02T	24LC02B	4L2BT				
24AA024	4A24T	24LC024	4L24T				
24AA025	4A25T	24LC025	4L25T				
				24C02C	4C2CT		
24AA04	4A04T	24LC04B	4L4BT				
24AA08	4A08T	24LC08B	4L8BT				
24AA16	4A16T	24LC16B	4L16T				
24AA32A	4A32AT	24LC32A	4L32AT				
24AA64	4A64T	24LC64	4L64T				
24AA128	4A128T	24LC128	4L128T			24FC128	4F128T
24AA256	4A256T	24LC256	4L256T			24FC256	4F256T

Note: T = Temperature range: I = Industrial, E = Extended, (blank) = Commercial

<p>Legend: XX...X Part number or part number code Y Year code (last digit of calendar year) YY Year code (last 2 digits of calendar year) WW Week code (week of January 1 is week '01') NNN Alphanumeric traceability code (2 characters for small packages) Ⓔ Pb-free JEDEC designator for Matte Tin (Sn) plated devices</p>
<p>Note: For very small packages with no room for the Pb-free JEDEC designator Ⓔ, the marking will only appear on the outer carton or reel label.</p>
<p>Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information.</p>

24AAXX/24LCXX/24FCXX

8-Lead TSSOP



Example:



8-Lead TSSOP Package Marking (Pb-free)

Device	Line 1 Marking	Device	Line 1 Marking	Device	Line 1 Marking	Device	Line 1 Marking
24AA00	4A00	24LC00	4L00	24C00	4C00		
24AA01	4A01	24LC01B	4L1B				
24AA014	4A14	24LC014	4L14				
				24C01C	4C1C		
24AA02	4A02	24LC02B	4L02				
24AA024	4A24	24LC024	4L24				
24AA025	4A25	24LC025	4L25				
				24C02C	4C2C		
24AA04	4A04	24LC04B	4L04				
24AA08	4A08	24LC08B	4L08				
24AA16	4A16	24LC16B	4L16				
24AA32A	4AA	24LC32A	4LA				
24AA64	4AB	24LC64	4LB				
24AA128	4AC	24LC128	4LC			24FC128	4FC
24AA256	4AD	24LC256	4LD			24FC256	4FD

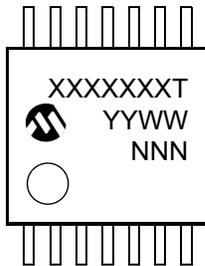
Note: T = Temperature range: I = Industrial, E = Extended, (blank) = Commercial

Legend:	XX...X	Part number or part number code
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week '01')
	NNN	Alphanumeric traceability code (2 characters for small packages)
	(e3)	Pb-free JEDEC designator for Matte Tin (Sn) plated devices

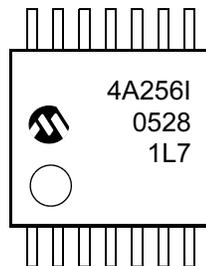
Note: For very small packages with no room for the Pb-free JEDEC designator (e3), the marking will only appear on the outer carton or reel label.

Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information.

14-Lead TSSOP



Example:



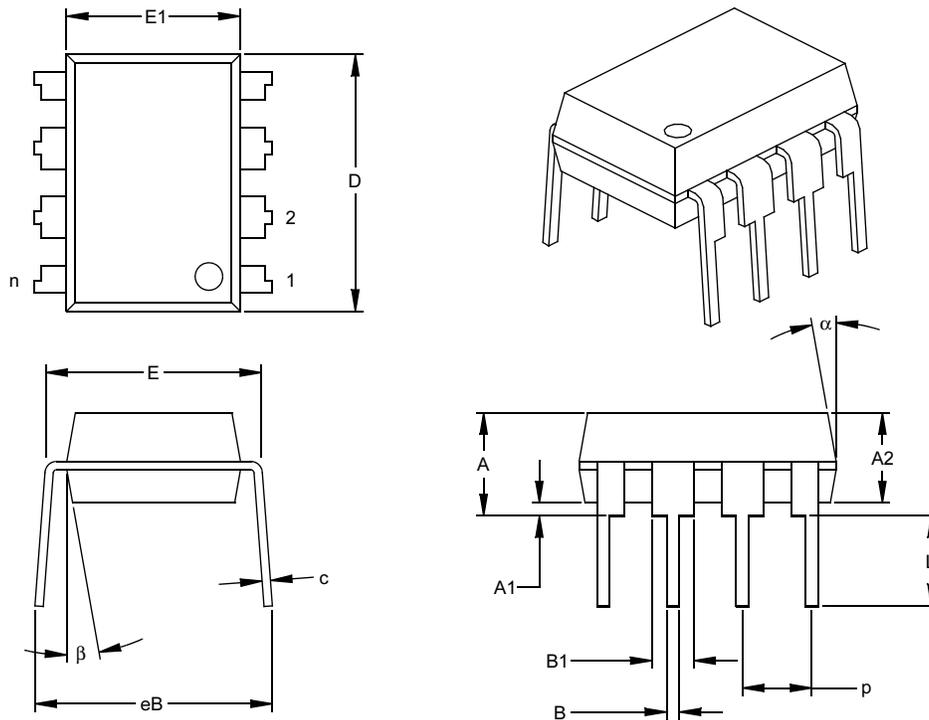
14-Lead TSSOP Package Marking (Pb-free)					
Device	Line 1 Marking	Device	Line 1 Marking	Device	Line 1 Marking
24AA128	4A128T	24LC128	4L128T	24FC128	4F128T
24AA256	4A256T	24LC256	4L256T	24FC256	4F256T
24AA512	4A512T	24LC512	4L512T	24FC512	4F512T

Note: T = Temperature range; I = Industrial, E = Extended

<p>Legend:</p> <ul style="list-style-type: none"> XX...X Part number or part number code Y Year code (last digit of calendar year) YY Year code (last 2 digits of calendar year) WW Week code (week of January 1 is week '01') NNN Alphanumeric traceability code (2 characters for small packages) (e3) Pb-free JEDEC designator for Matte Tin (Sn) plated devices
<p>Note: For very small packages with no room for the Pb-free JEDEC designator (e3), the marking will only appear on the outer carton or reel label.</p>
<p>Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information.</p>

24AAXX/24LCXX/24FCXX

8-Lead Plastic Dual In-line (P) – 300 mil (PDIP)



Dimension Limits	Units	INCHES*			MILLIMETERS		
		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		8			8	
Pitch	p		.100			2.54	
Top to Seating Plane	A	.140	.155	.170	3.56	3.94	4.32
Molded Package Thickness	A2	.115	.130	.145	2.92	3.30	3.68
Base to Seating Plane	A1	.015			0.38		
Shoulder to Shoulder Width	E	.300	.313	.325	7.62	7.94	8.26
Molded Package Width	E1	.240	.250	.260	6.10	6.35	6.60
Overall Length	D	.360	.373	.385	9.14	9.46	9.78
Tip to Seating Plane	L	.125	.130	.135	3.18	3.30	3.43
Lead Thickness	c	.008	.012	.015	0.20	0.29	0.38
Upper Lead Width	B1	.045	.058	.070	1.14	1.46	1.78
Lower Lead Width	B	.014	.018	.022	0.36	0.46	0.56
Overall Row Spacing	§ eB	.310	.370	.430	7.87	9.40	10.92
Mold Draft Angle Top	α	5	10	15	5	10	15
Mold Draft Angle Bottom	β	5	10	15	5	10	15

* Controlling Parameter

§ Significant Characteristic

Notes:

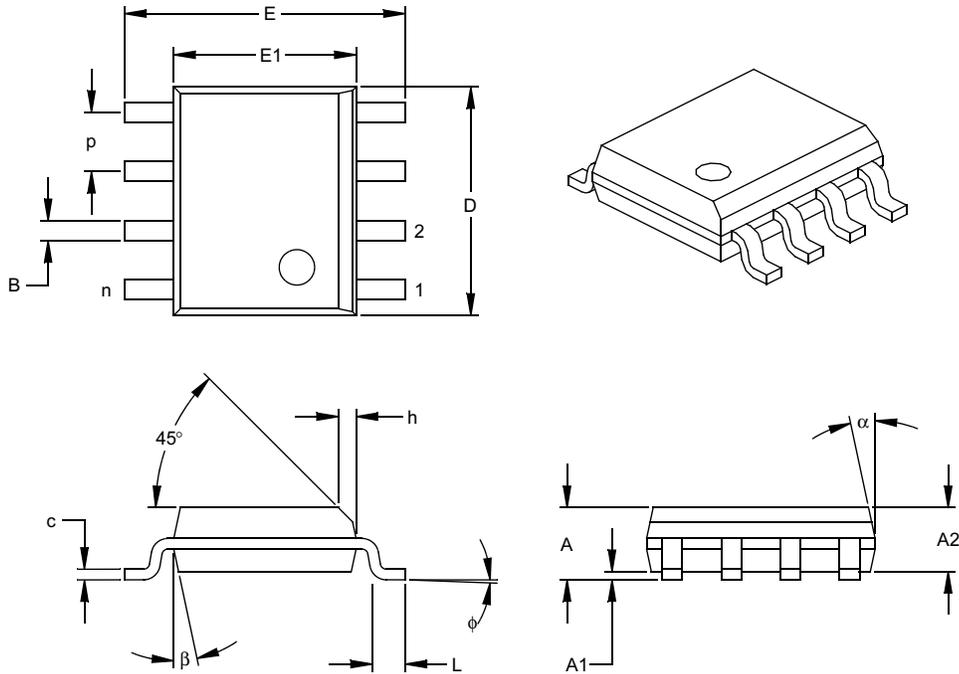
Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" (0.254mm) per side.

JEDEC Equivalent: MS-001

Drawing No. C04-018

24AAXX/24LCXX/24FCXX

8-Lead Plastic Small Outline (SN) – Narrow, 150 mil (SOIC)



Units		INCHES*			MILLIMETERS		
Dimension	Limits	MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		8			8	
Pitch	p		.050			1.27	
Overall Height	A	.053	.061	.069	1.35	1.55	1.75
Molded Package Thickness	A2	.052	.056	.061	1.32	1.42	1.55
Standoff §	A1	.004	.007	.010	0.10	0.18	0.25
Overall Width	E	.228	.237	.244	5.79	6.02	6.20
Molded Package Width	E1	.146	.154	.157	3.71	3.91	3.99
Overall Length	D	.189	.193	.197	4.80	4.90	5.00
Chamfer Distance	h	.010	.015	.020	0.25	0.38	0.51
Foot Length	L	.019	.025	.030	0.48	0.62	0.76
Foot Angle	φ	0	4	8	0	4	8
Lead Thickness	c	.008	.009	.010	0.20	0.23	0.25
Lead Width	B	.013	.017	.020	0.33	0.42	0.51
Mold Draft Angle Top	α	0	12	15	0	12	15
Mold Draft Angle Bottom	β	0	12	15	0	12	15

* Controlling Parameter
 § Significant Characteristic

Notes:

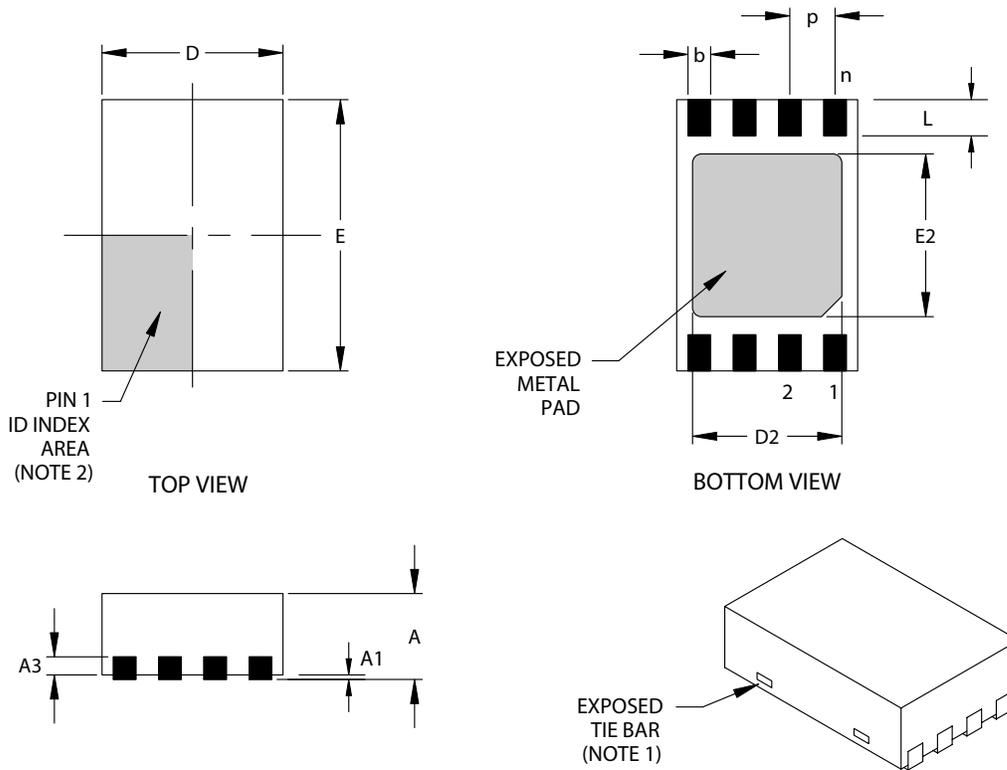
Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" (0.254mm) per side.

JEDEC Equivalent: MS-012

Drawing No. C04-057

24AAXX/24LCXX/24FCXX

8-Lead Plastic Dual Flat No Lead Package (MC) 2x3x0.9 mm Body (DFN) – Saw Singulated



Dimension Limits		Units	INCHES			MILLIMETERS*		
			MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		8			8		
Pitch	p		.020 BSC			0.50 BSC		
Overall Height	A		.031	.035	.039	0.80	0.90	1.00
Standoff	A1		.000	.001	.002	0.00	0.02	0.05
Contact Thickness	A3		.008 REF.			0.20 REF.		
Overall Length	D		.079 BSC			2.00 BSC		
Exposed Pad Length	(Note 3) D2		.055	--	.064	1.39	--	1.62
Overall Width	E		.118 BSC			3.00 BSC		
Exposed Pad Width	(Note 3) E2		.047	--	.071	1.20	--	1.80
Contact Width	b		.008	.010	.012	0.20	0.25	0.30
Contact Length	L		.012	.016	.020	0.30	0.40	0.50

*Controlling Parameter

Notes:

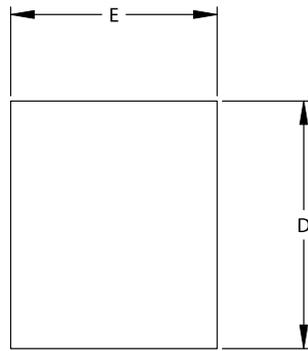
1. Package may have one or more exposed tie bars at ends.
2. Pin 1 visual index feature may vary, but must be located within the hatched area.
3. Exposed pad dimensions vary with paddle size.
4. JEDEC equivalent: MO-229

Drawing No. C04-123

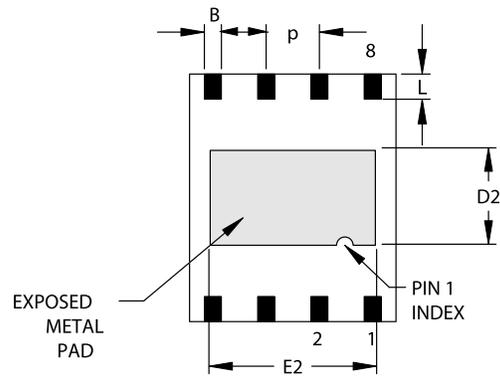
Revised 05/24/04

24AAXX/24LCXX/24FCXX

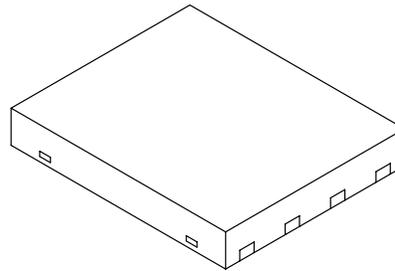
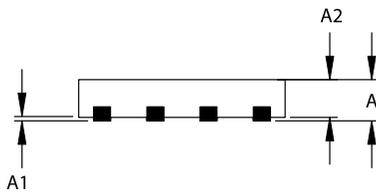
8-Lead Plastic Dual Flat No Lead Package (MF) 6x5 mm Body (DFN-S) – Saw Singulated



TOP VIEW



BOTTOM VIEW



Dimension Limits	Units	INCHES			MILLIMETERS*		
		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n	8			8		
Pitch	p	.050 BSC			1.27 BSC		
Overall Height	A	.033	.035	.037	0.85	0.90	0.95
Package Thickness	A2	.031	.035	.037	0.80	0.89	0.95
Standoff	A1	.000	.0004	.002	0.00	0.01	0.05
Base Thickness	A3	.007	.008	.009	0.17	0.20	0.23
Overall Length	E	.195	.197	.199	4.95	5.00	5.05
Exposed Pad Length	E2	.152	.157	.163	3.85	4.00	4.15
Overall Width	D	.234	.236	.238	5.95	6.00	6.05
Exposed Pad Width	D2	.089	.091	.093	2.25	2.30	2.35
Lead Width	B	.014	.016	.019	0.35	0.40	0.47
Lead Length	L	.024		.026	0.60		0.65

Notes:

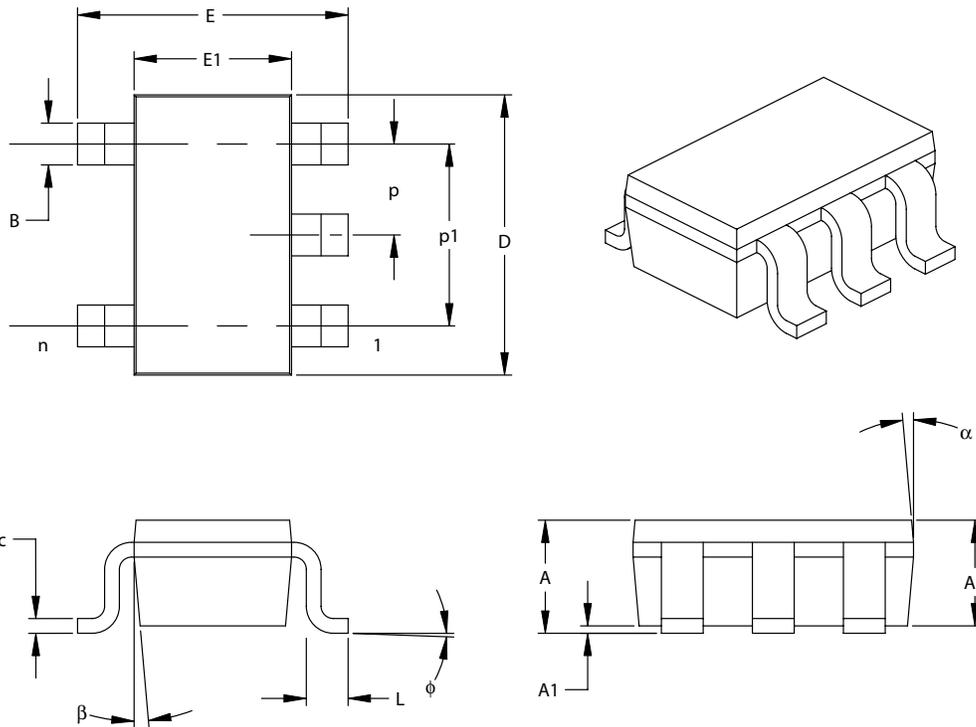
JEDEC equivalent: MO-220

Drawing No. C04-122

Revised 11/3/03

24AAXX/24LCXX/24FCXX

5-Lead Plastic Small Outline Transistor (OT) (SOT-23)



Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n	5			5		
Pitch	p		.038			0.95	
Outside lead pitch (basic)	p1		.075			1.90	
Overall Height	A	.035	.046	.057	0.90	1.18	1.45
Molded Package Thickness	A2	.035	.043	.051	0.90	1.10	1.30
Standoff	A1	.000	.003	.006	0.00	0.08	0.15
Overall Width	E	.102	.110	.118	2.60	2.80	3.00
Molded Package Width	E1	.059	.064	.069	1.50	1.63	1.75
Overall Length	D	.110	.116	.122	2.80	2.95	3.10
Foot Length	L	.014	.018	.022	0.35	0.45	0.55
Foot Angle	φ	0	5	10	0	5	10
Lead Thickness	c	.004	.006	.008	0.09	0.15	0.20
Lead Width	B	.014	.017	.020	0.35	0.43	0.50
Mold Draft Angle Top	α	0	5	10	0	5	10
Mold Draft Angle Bottom	β	0	5	10	0	5	10

*Controlling Parameter

Notes:

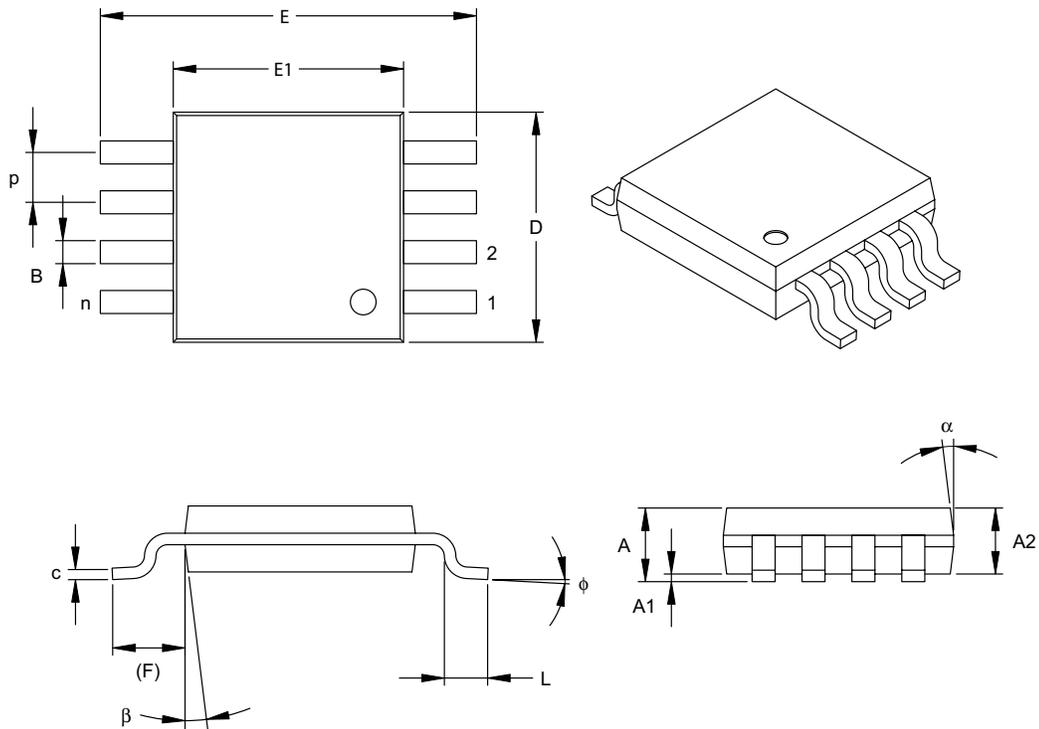
Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .005" (0.127mm) per side.

EIAJ Equivalent: SC-74A

Drawing No. C04-091

24AAXX/24LCXX/24FCXX

8-Lead Plastic Micro Small Outline Package (MS) (MSOP)



Dimension Limits	Units	INCHES			MILLIMETERS*		
		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n	8			8		
Pitch	P	.026 BSC			0.65 BSC		
Overall Height	A	-	-	.043	-	-	1.10
Molded Package Thickness	A2	.030	.033	.037	0.75	0.85	0.95
Standoff	A1	.000	-	.006	0.00	-	0.15
Overall Width	E	.193 TYP.			4.90 BSC		
Molded Package Width	E1	.118 BSC			3.00 BSC		
Overall Length	D	.118 BSC			3.00 BSC		
Foot Length	L	.016	.024	.031	0.40	0.60	0.80
Footprint (Reference)	F	.037 REF			0.95 REF		
Foot Angle	φ	0°	-	8°	0°	-	8°
Lead Thickness	c	.003	.006	.009	0.08	-	0.23
Lead Width	B	.009	.012	.016	0.22	-	0.40
Mold Draft Angle Top	α	5°	-	15°	5°	-	15°
Mold Draft Angle Bottom	β	5°	-	15°	5°	-	15°

*Controlling Parameter

Notes:

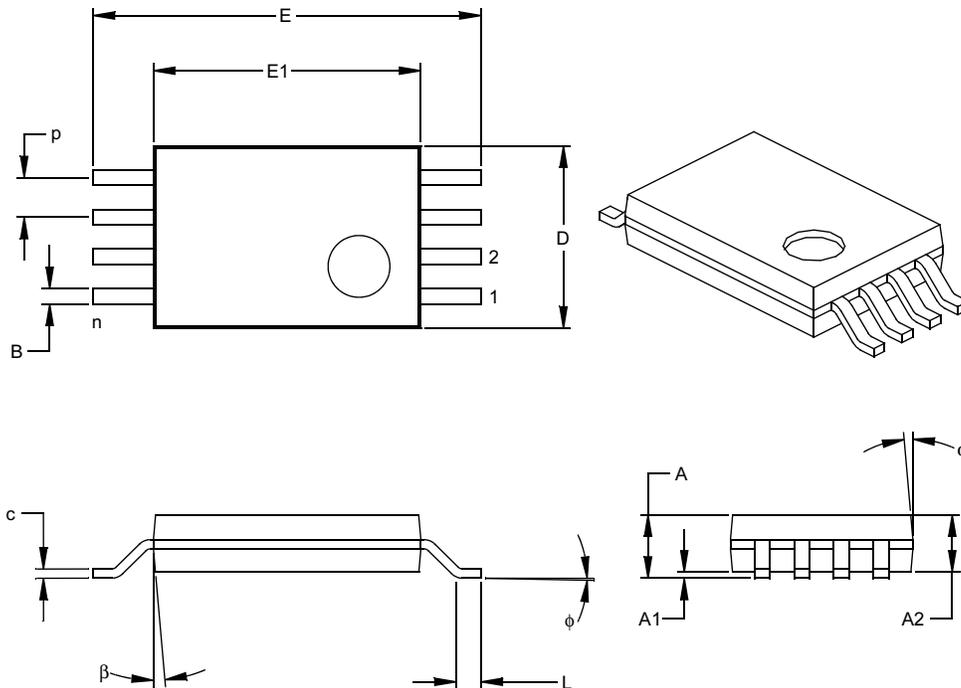
Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" (0.254mm) per side.

JEDEC Equivalent: MO-187

Drawing No. C04-111

24AAXX/24LCXX/24FCXX

8-Lead Plastic Thin Shrink Small Outline (ST) – 4.4 mm (TSSOP)



Dimension Limits	Units	INCHES			MILLIMETERS*		
	n	MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n			8			8
Pitch	p		.026			0.65	
Overall Height	A			.043			1.10
Molded Package Thickness	A2	.033	.035	.037	0.85	0.90	0.95
Standoff §	A1	.002	.004	.006	0.05	0.10	0.15
Overall Width	E	.246	.251	.256	6.25	6.38	6.50
Molded Package Width	E1	.169	.173	.177	4.30	4.40	4.50
Molded Package Length	D	.114	.118	.122	2.90	3.00	3.10
Foot Length	L	.020	.024	.028	0.50	0.60	0.70
Foot Angle	φ	0	4	8	0	4	8
Lead Thickness	c	.004	.006	.008	0.09	0.15	0.20
Lead Width	B	.007	.010	.012	0.19	0.25	0.30
Mold Draft Angle Top	α	0	5	10	0	5	10
Mold Draft Angle Bottom	β	0	5	10	0	5	10

* Controlling Parameter

§ Significant Characteristic

Notes:

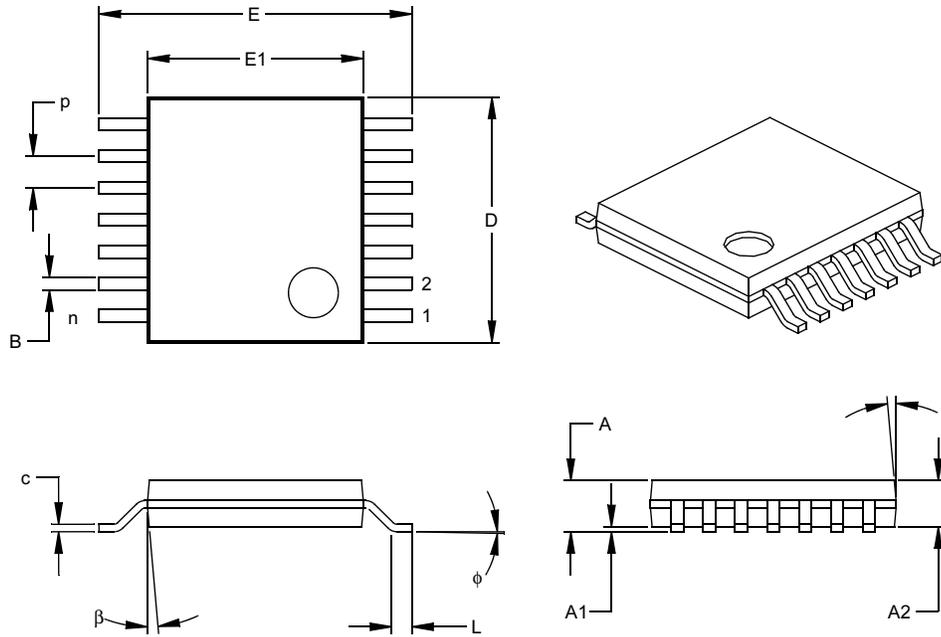
Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .005" (0.127mm) per side.

JEDEC Equivalent: MO-153

Drawing No. C04-086

24AAXX/24LCXX/24FCXX

14-Lead Plastic Thin Shrink Small Outline (ST) – 4.4 mm Body (TSSOP)



Dimension Limits	Units	INCHES			MILLIMETERS*		
		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n	14			14		
Pitch	p		.026			0.65	
Overall Height	A			.043			1.10
Molded Package Thickness	A2	.033	.035	.037	0.85	0.90	0.95
Standoff §	A1	.002	.004	.006	0.05	0.10	0.15
Overall Width	E	.246	.251	.256	6.25	6.38	6.50
Molded Package Width	E1	.169	.173	.177	4.30	4.40	4.50
Molded Package Length	D	.193	.197	.201	4.90	5.00	5.10
Foot Length	L	.020	.024	.028	0.50	0.60	0.70
Foot Angle	φ	0	4	8	0	4	8
Lead Thickness	c	.004	.006	.008	0.09	0.15	0.20
Lead Width	B	.007	.010	.012	0.19	0.25	0.30
Mold Draft Angle Top	α	0	5	10	0	5	10
Mold Draft Angle Bottom	β	0	5	10	0	5	10

* Controlling Parameter

§ Significant Characteristic

Notes:

Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .005" (0.127mm) per side.

JEDEC Equivalent: MO-153

Drawing No. C04-087

24AAXX/24LCXX/24FCXX

NOTES:

THE MICROCHIP WEB SITE

Microchip provides online support via our WWW site at www.microchip.com. This web site is used as a means to make files and information easily available to customers. Accessible by using your favorite Internet browser, the web site contains the following information:

- **Product Support** – Data sheets and errata, application notes and sample programs, design resources, user's guides and hardware support documents, latest software releases and archived software
- **General Technical Support** – Frequently Asked Questions (FAQ), technical support requests, online discussion groups, Microchip consultant program member listing
- **Business of Microchip** – Product selector and ordering guides, latest Microchip press releases, listing of seminars and events, listings of Microchip sales offices, distributors and factory representatives

CUSTOMER CHANGE NOTIFICATION SERVICE

Microchip's customer notification service helps keep customers current on Microchip products. Subscribers will receive e-mail notification whenever there are changes, updates, revisions or errata related to a specified product family or development tool of interest.

To register, access the Microchip web site at www.microchip.com, click on Customer Change Notification and follow the registration instructions.

CUSTOMER SUPPORT

Users of Microchip products can receive assistance through several channels:

- Distributor or Representative
- Local Sales Office
- Field Application Engineer (FAE)
- Technical Support
- Development Systems Information Line

Customers should contact their distributor, representative or field application engineer (FAE) for support. Local sales offices are also available to help customers. A listing of sales offices and locations is included in the back of this document.

Technical support is available through the web site at: <http://support.microchip.com>

In addition, there is a Development Systems Information Line which lists the latest versions of Microchip's development systems software products. This line also provides information on how customers can receive currently available upgrade kits.

The Development Systems Information Line numbers are:

1-800-755-2345 – United States and most of Canada

1-480-792-7302 – Other International Locations

PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

<u>PART NO.</u>	X	X	/XX	X																																																																																						
Device Part Number (Table 1-1)	Packaging Medium	Temperature Range	Package	Lead Finish																																																																																						
<table border="1" style="width: 100%;"> <tr> <td style="width: 15%;">Device:</td> <td colspan="4">See Table 1-1</td> </tr> <tr> <td>Temperature Range:</td> <td>I</td> <td>=</td> <td colspan="2">-40°C to +85°C</td> </tr> <tr> <td></td> <td>E</td> <td>=</td> <td colspan="2">-40°C to +125°C</td> </tr> <tr> <td></td> <td>C</td> <td>=</td> <td colspan="2">0°C to +70°C</td> </tr> <tr> <td>Packaging Medium:</td> <td>T</td> <td>=</td> <td colspan="2">Tape and Reel</td> </tr> <tr> <td></td> <td>Blank</td> <td>=</td> <td colspan="2">Tube</td> </tr> <tr> <td>Package:</td> <td>P</td> <td>=</td> <td colspan="2">Plastic DIP (300 mil body), 8-lead</td> </tr> <tr> <td></td> <td>SN</td> <td>=</td> <td colspan="2">Plastic SOIC (150 mil body), 8-lead</td> </tr> <tr> <td></td> <td>SM</td> <td>=</td> <td colspan="2">Plastic SOIC (208 mil body), 8-lead</td> </tr> <tr> <td></td> <td>ST</td> <td>=</td> <td colspan="2">Plastic TSSOP (4.4 mm), 8-lead</td> </tr> <tr> <td></td> <td>ST14</td> <td>=</td> <td colspan="2">Plastic TSSOP (4.4 mm), 14-lead</td> </tr> <tr> <td></td> <td>MS</td> <td>=</td> <td colspan="2">Plastic Micro Small Outline (MSOP), 8-lead</td> </tr> <tr> <td></td> <td>OT</td> <td>=</td> <td colspan="2">SOT-23, 5-lead (Tape and Reel only)</td> </tr> <tr> <td></td> <td>MC</td> <td>=</td> <td colspan="2">2x3 mm DFN, 8-lead</td> </tr> <tr> <td></td> <td>MF</td> <td>=</td> <td colspan="2">5x6 mm DFN, 8-lead</td> </tr> <tr> <td>Lead finish:</td> <td>Blank</td> <td>=</td> <td colspan="2">Pb-free – Matte Tin (see Note 1)</td> </tr> <tr> <td></td> <td>G</td> <td>=</td> <td colspan="2">Pb-free – Matte Tin only</td> </tr> </table>					Device:	See Table 1-1				Temperature Range:	I	=	-40°C to +85°C			E	=	-40°C to +125°C			C	=	0°C to +70°C		Packaging Medium:	T	=	Tape and Reel			Blank	=	Tube		Package:	P	=	Plastic DIP (300 mil body), 8-lead			SN	=	Plastic SOIC (150 mil body), 8-lead			SM	=	Plastic SOIC (208 mil body), 8-lead			ST	=	Plastic TSSOP (4.4 mm), 8-lead			ST14	=	Plastic TSSOP (4.4 mm), 14-lead			MS	=	Plastic Micro Small Outline (MSOP), 8-lead			OT	=	SOT-23, 5-lead (Tape and Reel only)			MC	=	2x3 mm DFN, 8-lead			MF	=	5x6 mm DFN, 8-lead		Lead finish:	Blank	=	Pb-free – Matte Tin (see Note 1)			G	=	Pb-free – Matte Tin only		Examples: a) 24C00/P: 128-bit, Commercial Temperature, 5V, PDIP package b) 24AA014-I/SN: 1 Kbit, Industrial Temperature, 1.8V, SOIC package c) 24AA02T-I/OT: 2 Kbit, Industrial Temperature, 1.8V, SOT-23 package, Tape and Reel d) 24LC16B-I/P: 16 Kbit, Industrial Temperature, 2.5V, PDIP package e) 24LC32A-E/MS: 32 Kbit, Extended Temperature, 2.5V, MSOP package f) 24LC64T-I/MC: 64 Kbit, Industrial Temperature, 2.5V 2x3 mm DFN package, Tape and Reel g) 24LC256-E/STG: 256 Kbit, Extended Temperature, 2.5V, TSSOP package, Pb-free h) 24FC512T-I/SM: 512 Kbit, Industrial Temperature, 1 MHz, SOIC package, Tape and Reel
Device:	See Table 1-1																																																																																									
Temperature Range:	I	=	-40°C to +85°C																																																																																							
	E	=	-40°C to +125°C																																																																																							
	C	=	0°C to +70°C																																																																																							
Packaging Medium:	T	=	Tape and Reel																																																																																							
	Blank	=	Tube																																																																																							
Package:	P	=	Plastic DIP (300 mil body), 8-lead																																																																																							
	SN	=	Plastic SOIC (150 mil body), 8-lead																																																																																							
	SM	=	Plastic SOIC (208 mil body), 8-lead																																																																																							
	ST	=	Plastic TSSOP (4.4 mm), 8-lead																																																																																							
	ST14	=	Plastic TSSOP (4.4 mm), 14-lead																																																																																							
	MS	=	Plastic Micro Small Outline (MSOP), 8-lead																																																																																							
	OT	=	SOT-23, 5-lead (Tape and Reel only)																																																																																							
	MC	=	2x3 mm DFN, 8-lead																																																																																							
	MF	=	5x6 mm DFN, 8-lead																																																																																							
Lead finish:	Blank	=	Pb-free – Matte Tin (see Note 1)																																																																																							
	G	=	Pb-free – Matte Tin only																																																																																							

Note 1: Most products manufactured after January 2005 have a Matte Tin (Pb-free) finish.

Most products manufactured before January 2005 have a finish of approximately 63% Sn and 37% Pb (Sn/Pb).

Please visit www.microchip.com/Pbfree for the latest information on Pb-free conversion, including conversion date codes.

Sales and Support

Data Sheets

Products supported by a preliminary Data Sheet may have an errata sheet describing minor operational differences and recommended workarounds. To determine if an errata sheet exists for a particular device, please contact one of the following:

1. Your local Microchip sales office
2. The Microchip Corporate Literature Center U.S. FAX: (480) 792-7277
3. The Microchip Worldwide Site (www.microchip.com)

Please specify which device, revision of silicon and Data Sheet (include Literature #) you are using.

Customer Notification System

Register on our web site (www.microchip.com/cn) to receive the most current information on our products.

24AAXX/24LCXX/24FCXX

NOTES:

Note the following details of the code protection feature on Microchip devices:

- Microchip products meet the specification contained in their particular Microchip Data Sheet.
- Microchip believes that its family of products is one of the most secure families of its kind on the market today, when used in the intended manner and under normal conditions.
- There are dishonest and possibly illegal methods used to breach the code protection feature. All of these methods, to our knowledge, require using the Microchip products in a manner outside the operating specifications contained in Microchip's Data Sheets. Most likely, the person doing so is engaged in theft of intellectual property.
- Microchip is willing to work with the customer who is concerned about the integrity of their code.
- Neither Microchip nor any other semiconductor manufacturer can guarantee the security of their code. Code protection does not mean that we are guaranteeing the product as "unbreakable."

Code protection is constantly evolving. We at Microchip are committed to continuously improving the code protection features of our products. Attempts to break Microchip's code protection feature may be a violation of the Digital Millennium Copyright Act. If such acts allow unauthorized access to your software or other copyrighted work, you may have a right to sue for relief under that Act.

Information contained in this publication regarding device applications and the like is provided only for your convenience and may be superseded by updates. It is your responsibility to ensure that your application meets with your specifications. MICROCHIP MAKES NO REPRESENTATIONS OR WARRANTIES OF ANY KIND WHETHER EXPRESS OR IMPLIED, WRITTEN OR ORAL, STATUTORY OR OTHERWISE, RELATED TO THE INFORMATION, INCLUDING BUT NOT LIMITED TO ITS CONDITION, QUALITY, PERFORMANCE, MERCHANTABILITY OR FITNESS FOR PURPOSE. Microchip disclaims all liability arising from this information and its use. Use of Microchip's products as critical components in life support systems is not authorized except with express written approval by Microchip. No licenses are conveyed, implicitly or otherwise, under any Microchip intellectual property rights.

Trademarks

The Microchip name and logo, the Microchip logo, Accuron, dsPIC, KEELOQ, microID, MPLAB, PIC, PICmicro, PICSTART, PRO MATE, PowerSmart, rPIC, and SmartShunt are registered trademarks of Microchip Technology Incorporated in the U.S.A. and other countries.

AmpLab, FilterLab, Migratable Memory, MXDEV, MXLAB, PICMASTER, SEEVAL, SmartSensor and The Embedded Control Solutions Company are registered trademarks of Microchip Technology Incorporated in the U.S.A.

Analog-for-the-Digital Age, Application Maestro, dsPICDEM, dsPICDEM.net, dsPICworks, ECAN, ECONOMONITOR, FanSense, FlexROM, fuzzyLAB, In-Circuit Serial Programming, ICSP, ICEPIC, Linear Active Thermistor, MPASM, MPLIB, MPLINK, MPSIM, PICkit, PICDEM, PICDEM.net, PICLAB, PICtail, PowerCal, PowerInfo, PowerMate, PowerTool, rLAB, rPICDEM, Select Mode, Smart Serial, SmartTel, Total Endurance and WiperLock are trademarks of Microchip Technology Incorporated in the U.S.A. and other countries.

SQTP is a service mark of Microchip Technology Incorporated in the U.S.A.

All other trademarks mentioned herein are property of their respective companies.

© 2005, Microchip Technology Incorporated, Printed in the U.S.A., All Rights Reserved.

 Printed on recycled paper.

QUALITY MANAGEMENT SYSTEM
CERTIFIED BY DNV
== ISO/TS 16949:2002 ==

Microchip received ISO/TS-16949:2002 quality system certification for its worldwide headquarters, design and wafer fabrication facilities in Chandler and Tempe, Arizona and Mountain View, California in October 2003. The Company's quality system processes and procedures are for its PICmicro® 8-bit MCUs, KEELOQ® code hopping devices, Serial EEPROMs, microperipherals, nonvolatile memory and analog products. In addition, Microchip's quality system for the design and manufacture of development systems is ISO 9001:2000 certified.



WORLDWIDE SALES AND SERVICE

AMERICAS

Corporate Office
2355 West Chandler Blvd.
Chandler, AZ 85224-6199
Tel: 480-792-7200
Fax: 480-792-7277
Technical Support:
<http://support.microchip.com>
Web Address:
www.microchip.com

Atlanta

Alpharetta, GA
Tel: 770-640-0034
Fax: 770-640-0307

Boston

Westborough, MA
Tel: 774-760-0087
Fax: 774-760-0088

Chicago

Itasca, IL
Tel: 630-285-0071
Fax: 630-285-0075

Dallas

Addison, TX
Tel: 972-818-7423
Fax: 972-818-2924

Detroit

Farmington Hills, MI
Tel: 248-538-2250
Fax: 248-538-2260

Kokomo

Kokomo, IN
Tel: 765-864-8360
Fax: 765-864-8387

Los Angeles

Mission Viejo, CA
Tel: 949-462-9523
Fax: 949-462-9608

San Jose

Mountain View, CA
Tel: 650-215-1444
Fax: 650-961-0286

Toronto

Mississauga, Ontario,
Canada
Tel: 905-673-0699
Fax: 905-673-6509

ASIA/PACIFIC

Australia - Sydney
Tel: 61-2-9868-6733
Fax: 61-2-9868-6755

China - Beijing
Tel: 86-10-8528-2100
Fax: 86-10-8528-2104

China - Chengdu
Tel: 86-28-8676-6200
Fax: 86-28-8676-6599

China - Fuzhou
Tel: 86-591-8750-3506
Fax: 86-591-8750-3521

China - Hong Kong SAR
Tel: 852-2401-1200
Fax: 852-2401-3431

China - Shanghai
Tel: 86-21-5407-5533
Fax: 86-21-5407-5066

China - Shenyang
Tel: 86-24-2334-2829
Fax: 86-24-2334-2393

China - Shenzhen
Tel: 86-755-8203-2660
Fax: 86-755-8203-1760

China - Shunde
Tel: 86-757-2839-5507
Fax: 86-757-2839-5571

China - Qingdao
Tel: 86-532-502-7355
Fax: 86-532-502-7205

ASIA/PACIFIC

India - Bangalore
Tel: 91-80-2229-0061
Fax: 91-80-2229-0062

India - New Delhi
Tel: 91-11-5160-8631
Fax: 91-11-5160-8632

Japan - Kanagawa
Tel: 81-45-471-6166
Fax: 81-45-471-6122

Korea - Seoul
Tel: 82-2-554-7200
Fax: 82-2-558-5932 or
82-2-558-5934

Malaysia - Penang
Tel: 011-604-646-8870
Fax: 011-604-646-5086

Philippines - Manila
Tel: 011-632-634-9065
Fax: 011-632-634-9069

Singapore
Tel: 65-6334-8870
Fax: 65-6334-8850

Taiwan - Kaohsiung
Tel: 886-7-536-4818
Fax: 886-7-536-4803

Taiwan - Taipei
Tel: 886-2-2500-6610
Fax: 886-2-2508-0102

Taiwan - Hsinchu
Tel: 886-3-572-9526
Fax: 886-3-572-6459

EUROPE

Austria - Weis
Tel: 43-7242-2244-399
Fax: 43-7242-2244-393

Denmark - Ballerup
Tel: 45-4450-2828
Fax: 45-4485-2829

France - Massy
Tel: 33-1-69-53-63-20
Fax: 33-1-69-30-90-79

Germany - Ismaning
Tel: 49-89-627-144-0
Fax: 49-89-627-144-44

Italy - Milan
Tel: 39-0331-742611
Fax: 39-0331-466781

Netherlands - Drunen
Tel: 31-416-690399
Fax: 31-416-690340

England - Berkshire
Tel: 44-118-921-5869
Fax: 44-118-921-5820